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LED LCD TV

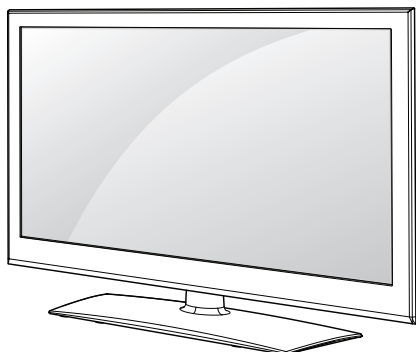
SERVICE MANUAL

CHASSIS : LB01M

MODEL : 32LV3400 32LV3400-TG

CAUTION

BEFORE SERVICING THE CHASSIS,
READ THE SAFETY PRECAUTIONS IN THIS MANUAL.



P/NO : MFL67002741 (1108-REV00)

Printed in Korea

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SAFETY PRECAUTIONS

IMPORTANT SAFETY NOTICE

Many electrical and mechanical parts in this chassis have special safety-related characteristics. These parts are identified by \triangle in the Schematic Diagram and Exploded View.

It is essential that these special safety parts should be replaced with the same components as recommended in this manual to prevent Shock, Fire, or other Hazards.

Do not modify the original design without permission of manufacturer.

General Guidance

An **isolation Transformer** should always be used during the servicing of a receiver whose chassis is not isolated from the AC power line. Use a transformer of adequate power rating as this protects the technician from accidents resulting in personal injury from electrical shocks.

It will also protect the receiver and its components from being damaged by accidental shorts of the circuitry that may be inadvertently introduced during the service operation.

If any fuse(or Fusible Resistor) in this TV receiver is blown, replace it with the specified.

When replacing a high wattage resistor (Oxide Metal Film Resistor, over 1 W), keep the resistor 10mm away from PCB.

Keep wires away from high voltage or high temperature parts.

Before returning the receiver to the customer,

always perform an **AC leakage current check** on the exposed metallic parts of the cabinet, such as antennas, terminals, etc., to be sure the set is safe to operate without damage of electrical shock.

Leakage Current Cold Check(Antenna Cold Check)

With the instrument AC plug removed from AC source, connect an electrical jumper across the two AC plug prongs. Place the AC switch in the on position, connect one lead of ohm-meter to the AC plug prongs tied together and touch other ohm-meter lead in turn to each exposed metallic parts such as antenna terminals, phone jacks, etc.

If the exposed metallic part has a return path to the chassis, the measured resistance should be between 1 M Ω and 5.2 M Ω .

When the exposed metal has no return path to the chassis the reading must be infinite.

An other abnormality exists that must be corrected before the receiver is returned to the customer.

Leakage Current Hot Check (See below Figure)

Plug the AC cord directly into the AC outlet.

Do not use a line Isolation Transformer during this check.

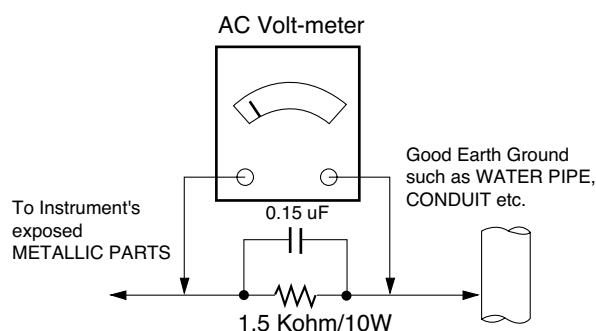
Connect 1.5 K / 10 watt resistor in parallel with a 0.15 μ F capacitor between a known good earth ground (Water Pipe, Conduit, etc.) and the exposed metallic parts.

Measure the AC voltage across the resistor using AC voltmeter with 1000 ohms/volt or more sensitivity.

Reverse plug the AC cord into the AC outlet and repeat AC voltage measurements for each exposed metallic part. Any voltage measured must not exceed 0.75 volt RMS which corresponds to 0.5 mA.

In case any measurement is out of the limits specified, there is possibility of shock hazard and the set must be checked and repaired before it is returned to the customer.

Leakage Current Hot Check circuit



When 25A is impressed between Earth and 2nd Ground for 1 second, Resistance must be less than 0.1 Ω

*Base on Adjustment standard

SERVICING PRECAUTIONS

CAUTION: Before servicing receivers covered by this service manual and its supplements and addenda, read and follow the SAFETY PRECAUTIONS on page 3 of this publication.

NOTE: If unforeseen circumstances create conflict between the following servicing precautions and any of the safety precautions on page 3 of this publication, always follow the safety precautions. Remember: Safety First.

General Servicing Precautions

1. Always unplug the receiver AC power cord from the AC power source before;
 - a. Removing or reinstalling any component, circuit board module or any other receiver assembly.
 - b. Disconnecting or reconnecting any receiver electrical plug or other electrical connection.
 - c. Connecting a test substitute in parallel with an electrolytic capacitor in the receiver.
CAUTION: A wrong part substitution or incorrect polarity installation of electrolytic capacitors may result in an explosion hazard.
2. Test high voltage only by measuring it with an appropriate high voltage meter or other voltage measuring device (DVM, FETVOM, etc) equipped with a suitable high voltage probe. Do not test high voltage by "drawing an arc".
3. Do not spray chemicals on or near this receiver or any of its assemblies.
4. Unless specified otherwise in this service manual, clean electrical contacts only by applying the following mixture to the contacts with a pipe cleaner, cotton-tipped stick or comparable non-abrasive applicator; 10 % (by volume) Acetone and 90 % (by volume) isopropyl alcohol (90 % - 99 % strength)
CAUTION: This is a flammable mixture.
Unless specified otherwise in this service manual, lubrication of contacts is not required.
5. Do not defeat any plug/socket B+ voltage interlocks with which receivers covered by this service manual might be equipped.
6. Do not apply AC power to this instrument and/or any of its electrical assemblies unless all solid-state device heat sinks are correctly installed.
7. Always connect the test receiver ground lead to the receiver chassis ground before connecting the test receiver positive lead.
Always remove the test receiver ground lead last.
8. Use with this receiver only the test fixtures specified in this service manual.
CAUTION: Do not connect the test fixture ground strap to any heat sink in this receiver.

Electrostatically Sensitive (ES) Devices

Some semiconductor (solid-state) devices can be damaged easily by static electricity. Such components commonly are called Electrostatically Sensitive (ES) Devices. Examples of typical ES devices are integrated circuits and some field-effect transistors and semiconductor "chip" components. The following techniques should be used to help reduce the incidence of component damage caused by static by static electricity.

1. Immediately before handling any semiconductor component or semiconductor-equipped assembly, drain off any electrostatic charge on your body by touching a known earth ground. Alternatively, obtain and wear a commercially available discharging wrist strap device, which should be removed to prevent potential shock reasons prior to applying power to the unit under test.

2. After removing an electrical assembly equipped with ES devices, place the assembly on a conductive surface such as aluminum foil, to prevent electrostatic charge buildup or exposure of the assembly.
3. Use only a grounded-tip soldering iron to solder or unsolder ES devices.
4. Use only an anti-static type solder removal device. Some solder removal devices not classified as "anti-static" can generate electrical charges sufficient to damage ES devices.
5. Do not use freon-propelled chemicals. These can generate electrical charges sufficient to damage ES devices.
6. Do not remove a replacement ES device from its protective package until immediately before you are ready to install it. (Most replacement ES devices are packaged with leads electrically shorted together by conductive foam, aluminum foil or comparable conductive material).
7. Immediately before removing the protective material from the leads of a replacement ES device, touch the protective material to the chassis or circuit assembly into which the device will be installed.
CAUTION: Be sure no power is applied to the chassis or circuit, and observe all other safety precautions.
8. Minimize bodily motions when handling unpackaged replacement ES devices. (Otherwise harmless motion such as the brushing together of your clothes fabric or the lifting of your foot from a carpeted floor can generate static electricity sufficient to damage an ES device.)

General Soldering Guidelines

1. Use a grounded-tip, low-wattage soldering iron and appropriate tip size and shape that will maintain tip temperature within the range or 500 °F to 600 °F.
2. Use an appropriate gauge of RMA resin-core solder composed of 60 parts tin/40 parts lead.
3. Keep the soldering iron tip clean and well tinned.
4. Thoroughly clean the surfaces to be soldered. Use a mall wire-bristle (0.5 inch, or 1.25 cm) brush with a metal handle. Do not use freon-propelled spray-on cleaners.
5. Use the following unsoldering technique
 - a. Allow the soldering iron tip to reach normal temperature. (500 °F to 600 °F)
 - b. Heat the component lead until the solder melts.
 - c. Quickly draw the melted solder with an anti-static, suction-type solder removal device or with solder braid.
CAUTION: Work quickly to avoid overheating the circuit board printed foil.
6. Use the following soldering technique.
 - a. Allow the soldering iron tip to reach a normal temperature (500 °F to 600 °F)
 - b. First, hold the soldering iron tip and solder the strand against the component lead until the solder melts.
 - c. Quickly move the soldering iron tip to the junction of the component lead and the printed circuit foil, and hold it there only until the solder flows onto and around both the component lead and the foil.
CAUTION: Work quickly to avoid overheating the circuit board printed foil.
 - d. Closely inspect the solder area and remove any excess or splashed solder with a small wire-bristle brush.

IC Remove/Replacement

Some chassis circuit boards have slotted holes (oblong) through which the IC leads are inserted and then bent flat against the circuit foil. When holes are the slotted type, the following technique should be used to remove and replace the IC. When working with boards using the familiar round hole, use the standard technique as outlined in paragraphs 5 and 6 above.

Removal

1. Desolder and straighten each IC lead in one operation by gently prying up on the lead with the soldering iron tip as the solder melts.
2. Draw away the melted solder with an anti-static suction-type solder removal device (or with solder braid) before removing the IC.

Replacement

1. Carefully insert the replacement IC in the circuit board.
2. Carefully bend each IC lead against the circuit foil pad and solder it.
3. Clean the soldered areas with a small wire-bristle brush.
(It is not necessary to reapply acrylic coating to the areas).

"Small-Signal" Discrete Transistor

Removal/Replacement

1. Remove the defective transistor by clipping its leads as close as possible to the component body.
2. Bend into a "U" shape the end of each of three leads remaining on the circuit board.
3. Bend into a "U" shape the replacement transistor leads.
4. Connect the replacement transistor leads to the corresponding leads extending from the circuit board and crimp the "U" with long nose pliers to insure metal to metal contact then solder each connection.

Power Output, Transistor Device

Removal/Replacement

1. Heat and remove all solder from around the transistor leads.
2. Remove the heat sink mounting screw (if so equipped).
3. Carefully remove the transistor from the heat sink of the circuit board.
4. Insert new transistor in the circuit board.
5. Solder each transistor lead, and clip off excess lead.
6. Replace heat sink.

Diode Removal/Replacement

1. Remove defective diode by clipping its leads as close as possible to diode body.
2. Bend the two remaining leads perpendicular y to the circuit board.
3. Observing diode polarity, wrap each lead of the new diode around the corresponding lead on the circuit board.
4. Securely crimp each connection and solder it.
5. Inspect (on the circuit board copper side) the solder joints of the two "original" leads. If they are not shiny, reheat them and if necessary, apply additional solder.

Fuse and Conventional Resistor

Removal/Replacement

1. Clip each fuse or resistor lead at top of the circuit board hollow stake.
2. Securely crimp the leads of replacement component around notch at stake top.
3. Solder the connections.

CAUTION: Maintain original spacing between the replaced component and adjacent components and the circuit board to prevent excessive component temperatures.

Circuit Board Foil Repair

Excessive heat applied to the copper foil of any printed circuit board will weaken the adhesive that bonds the foil to the circuit board causing the foil to separate from or "lift-off" the board. The following guidelines and procedures should be followed whenever this condition is encountered.

At IC Connections

To repair a defective copper pattern at IC connections use the following procedure to install a jumper wire on the copper pattern side of the circuit board. (Use this technique only on IC connections).

1. Carefully remove the damaged copper pattern with a sharp knife. (Remove only as much copper as absolutely necessary).
2. carefully scratch away the solder resist and acrylic coating (if used) from the end of the remaining copper pattern.
3. Bend a small "U" in one end of a small gauge jumper wire and carefully crimp it around the IC pin. Solder the IC connection.
4. Route the jumper wire along the path of the out-away copper pattern and let it overlap the previously scraped end of the good copper pattern. Solder the overlapped area and clip off any excess jumper wire.

At Other Connections

Use the following technique to repair the defective copper pattern at connections other than IC Pins. This technique involves the installation of a jumper wire on the component side of the circuit board.

1. Remove the defective copper pattern with a sharp knife.
Remove at least 1/4 inch of copper, to ensure that a hazardous condition will not exist if the jumper wire opens.
2. Trace along the copper pattern from both sides of the pattern break and locate the nearest component that is directly connected to the affected copper pattern.
3. Connect insulated 20-gauge jumper wire from the lead of the nearest component on one side of the pattern break to the lead of the nearest component on the other side.
Carefully crimp and solder the connections.

CAUTION: Be sure the insulated jumper wire is dressed so the it does not touch components or sharp edges.

SPECIFICATION

NOTE : Specifications and others are subject to change without notice for improvement.

1. Application range

This specification is applied to the LCD TV used LB01M chassis.

2. Requirement for Test

Each part is tested as below without special appointment.

- 1) Temperature: 25 °C ± 5 °C(77 °F ± 9 °F), CST: 40 °C ± 5 °C
- 2) Relative Humidity : 65 % ± 10 %
- 3) Power Voltage
 - : Standard input voltage(100 V - 240 V, 50 / 60Hz)
 - * Standard Voltage of each products is marked by models.
- 4) Specification and performance of each parts are followed each drawing and specification by part number in accordance with BOM.
- 5) The receiver must be operated for about 5 minutes prior to the adjustment.

3. Test method

- 1) Performance: LGE TV test method followed
- 2) Demanded other specification
 - Safety: CE, IEC specification
 - EMC:CE, IEC

4. Model General Specification

No.	Item	Specification	Remarks
1.	Market	Australia, New Zealand, Singapore, Malaysia, Vietnam, Indonesia, South Africa, Israel, A-ASIA	only Analog for A-ASIA
2.	Broadcasting system	1) PAL/SECAM-B/G/D/K 2) PAL-I/II 3) NTSC-M 4) DVB-T	PAL for NZ/SG
3.	Receiving system	Analog : Upper Heterodyne Digital : COFDM(DVB-T)	► DVB-T - Guard Interval(Bitrate_Mbit/s) 1/4, 1/8, 1/16, 1/32 - Modulation : Code Rate QPSK : 1/2, 2/3, 3/4, 5/6, 7/8 16-QAM : 1/2, 2/3, 3/4, 5/6, 7/8 64-QAM : 1/2, 2/3, 3/4, 5/6, 7/8
4.	Video Input RCA	PAL, SECAM, NTSC	4 System : PAL, SECAM, NTSC, PAL60
5.	Component Input	Y/Cb/Cr, Y/Pb/Pr	
6.	RGB Input (1EA)	RGB-PC	Analog(D-SUB 15PIN)
7.	HDMI Input	HDMI1-DTV/DVI HDMI2-DTV/DVI HDMI3-DTV/DVI	PC - HD Model : HDMI version 1.3 - FHD Model : HDMI version 1.4 Support HDCP
8.	Audio Input	RGB/DVI Audio Component AV	
9.	SDPIF out	SPDIF out	
10.	USB	For My Media(Movie/Photo/Music List) or For SVC	

5. Component Video Input (Y, C_B/P_B, C_R/P_R)

No	Specification				Remark
	Resolution	H-freq(kHz)	V-freq(Hz)		
1.	720x480	15.73	60.00	SDTV,DVD 480i	
2.	720x480	15.63	59.94	SDTV,DVD 480i	
3.	720x480	31.47	59.94	480p	
4.	720x480	31.50	60.00	480p	
5.	720x576	15.625	50.00	SDTV,DVD 625 Line	
6.	720x576	31.25	50.00	HDTV 576p	
7.	1280x720	45.00	50.00	HDTV 720p	
8.	1280x720	44.96	59.94	HDTV 720p	
9.	1280x720	45.00	60.00	HDTV 720p	
10.	1920x1080	31.25	50.00	HDTV 1080i	
11.	1920x1080	33.75	60.00	HDTV 1080i	
12.	1920x1080	33.72	59.94	HDTV 1080i	
13.	1920x1080	56.250	50	HDTV 1080p	
14.	1920x1080	67.5	60	HDTV 1080p	

6. RGB (PC)

No	Specification				Proposed	Remark
	Resolution	H-freq(kHz)	V-freq(Hz)	Pixel Clock(MHz)		
1.	720*400	31.468	70.08	28.321		For only DOS mode
2.	640*480	31.469	59.94	25.17	VESA	Input 848*480 60 Hz, 852*480 60 Hz -> 640*480 60 Hz Display
3.	800*600	37.879	60.31	40.00	VESA	
4.	1024*768	48.363	60.00	65.00	VESA(XGA)	
5.	1280*768	47.78	59.87	79.5	WXGA	
6.	1360*768	47.72	59.8	84.75	WXGA	
7.	1280*1024	63.595	60.0	108.875	SXGA	FHD model
8.	1920*1080	66.587	59.93	138.5	WUXGA	FHD model

7. HDMI Input (PC/DTV)

(1) DTV Mode

No	Resolution	H-freq(kHz)	V-freq.(Hz)	Pixel clock(MHz)	Proposed	Remark
1.	720*480	31.469 / 31.5	59.94 / 60	27.00 / 27.03	SDTV 480P	
2.	720*576	31.25	50	54	SDTV 576P	
3.	1280*720	37.500	50	74.25	HDTV 720P	
4.	1280*720	44.96 / 45	59.94 / 60	74.17 / 74.25	HDTV 720P	
5.	1920*1080	33.72 / 33.75	59.94 / 60	74.17 / 74.25	HDTV 1080I	
6.	1920*1080	28.125	50.00	74.25	HDTV 1080I	
7.	1920*1080	26.97 / 27	23.97 / 24	74.17 / 74.25	HDTV 1080P	
8.	1920*1080	33.716 / 33.75	29.976 / 30.00	74.25	HDTV 1080P	
9.	1920*1080	56.250	50	148.5	HDTV 1080P	
10.	1920*1080	67.43 / 67.5	59.94 / 60	148.35 / 148.50	HDTV 1080P	

(2) PC Mode

No	Resolution	H-freq(kHz)	V-freq.(Hz)	Pixel clock(MHz)	Proposed	Remark
1.	720*400	31.468	70.08	28.321		HDCP
2.	640*480	31.469	59.94	25.17	VESA	HDCP
3.	800*600	37.879	60.31	40.00	VESA	HDCP
4.	1024*768	48.363	60.00	65.00	VESA(XGA)	HDCP
5.	1360*768	47.72	59.8	84.75	WXGA	HDCP
6.	1280*1024	63.595	60.0	108.875	SXGA	HDCP
7.	1920*1080	67.5	60	148.5	WUXGA	HDCP

ADJUSTMENT INSTRUCTION

1. Application Range

This specification sheet is applied to all of the LCD TV with LB01M chassis.

2. Designation

- 1) The adjustment is according to the order which is designated and which must be followed, according to the plan which can be changed only on agreeing.
- 2) Power Adjustment: Free Voltage
- 3) Magnetic Field Condition: Nil.
- 4) Input signal Unit: Product Specification Standard
- 5) Reserve after operation: Above 5 Minutes (Heat Run)
Temperature : at 25 °C ± 5 °C
Relative humidity : 65 % ± 10 %
Input voltage : 220 V, 60 Hz
- 6) Adjustment equipments: Color Analyzer (CA-210 or CA-110), Pattern Generator(MSPG-925L or Equivalent), DDC Adjustment Jig equipment, Service remote control.
- 7) Push The "IN STOP KEY" - For memory initialization.

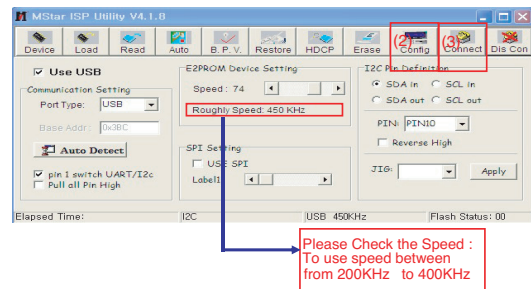
Case1 : Software version up

1. After downloading S/W by USB, TV set will reboot automatically.
2. Push "In-stop" key.
3. Push "Power on" key.
4. Function inspection
5. After function inspection, Push "In-stop" key.

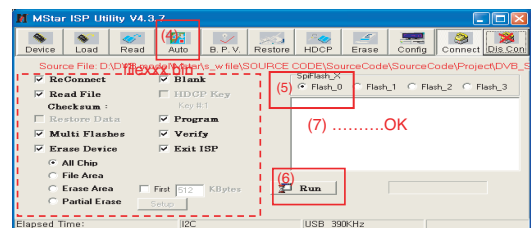
Case2 : Function check at the assembly line

1. When TV set is entering on the assembly line, Push "In-stop" key at first.
2. Push "Power on" key for turning it on.
-> If you push "Power on" key, TV set will recover channel information by itself.
3. After function inspection, Push "In-stop" key.

- 4) Click "Connect" tab. If "Can't" is displayed, check connection between computer, jig, and set.

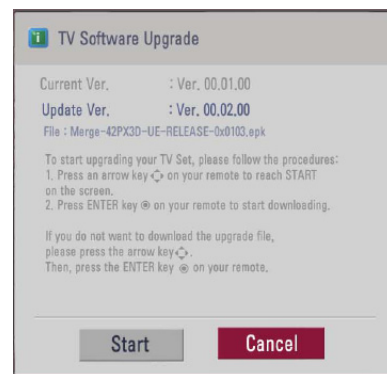


- 5) Click "Auto" tab and set as below.
- 6) Click "Run".
- 7) After downloading, check "OK" message.

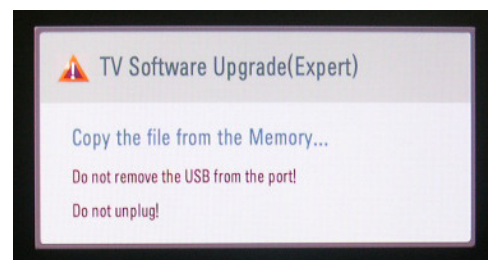


* USB DOWNLOAD(*.epk file download)

- 1) Put the USB Stick to the USB socket.
- 2) Automatically detecting update file in USB Stick
- If version of update file in USB Stick is Lower, it didn't work. But version of update file is Higher, USB data is automatically detecting.



- 3) Show the message "Copying files from memory"

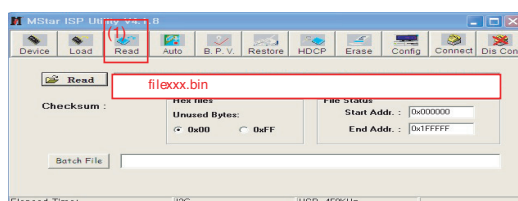


3. Main PCB check process

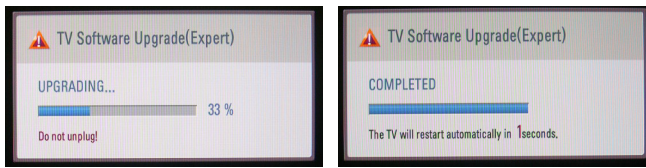
* APC - After Manual-Insert, executing APC

* Boot file Download

- 1) Execute ISP program "Mstar ISP Utility" and then click "Config" tab.
- 2) Set as below, and then click "Auto Detect" and check "OK" message. If "Error" is displayed, Check connection between computer, jig, and set.
- 3) Click "Read" tab, and then load download file(XXXX.bin) by clicking "Read".



(4) Updating is starting.



(5) After updating is complete, the TV will restart automatically.
 (6) If TV turns on, check your updated version and Tool option.
 (refer to the next page about tool option)

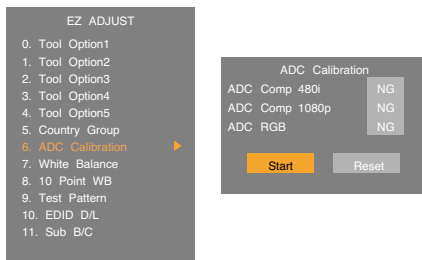
* If downloading version is higher than your TV have, TV can lost all channel data. In this case, you have to channel recover. If all channel data is cleared, you didn't have a DTV/ATV test on production line.

*** After downloading, have to adjust Tool Option again.**

- (1) Push "IN-START" key in service manual control.
- (2) Select 'Tool Option 1' and push 'OK' key.
- (3) Punch in the number. (Each models has their number.)
- (4) Correction Tool option is completed.

3.1. ADC Process

- Enter 'EZ ADJUST' mode by pushing 'ADJ' key,
- Enter Internal ADC mode by pushing '►' key at "6. ADC Calibration".



<Caution> Using 'P-ONLY' key of the Adjustment remote control, power on TV.

*** ADC Calibration Protocol (RS232)**

No	Item	CMD1	CMD2	Data0	
Enter Adjust Mode	Adjust 'Mode In'	A	A	0 0	When transfer the 'Mode In', Carry the command.
ADC adjust	ADC Adjust	A	D	1 0	Automatically adjustment (The use of a internal pattern)

Adjust Sequence

- aa 00 00 [Enter Adjust Mode]
- xb 00 40 [Component1 Input (480i)]
- ad 00 10 [Adjust 480i Comp1]
- xb 00 60 [RGB Input (1024*768)]
- ad 00 10 [Adjust 1024*768 RGB]
- aa 00 90 End Adjust mode
- * Required equipment : factory Service Remote control

3.2. Function Check

- (1) Check display and sound
 - Check Input and Signal items. (cf. work instructions)
 - 1) TV
 - 2) AV
 - 3) COMPONENT1/2 (480i)
 - 4) RGB (PC : 1024 x 768 @ 60hz)
 - 5) HDMI
 - 6) PC Audio In
- * Display and Sound check is executed by remote control.

<Caution> Not to push the INSTOP key after completion if the function inspection.

4. Total Assembly line process

4.1. Adjustment Preparation

- W/B Equipment condition
 CA210
 - CCFL/EEFL -> CH 9, Test signal : Inner pattern(80 IRE)
 - LED(AUO) -> CH 14, Test signal : Inner pattern(80 IRE)
- Above 5 minutes H/run in the inner pattern. ("power on" key of adjustment remote control)

Cool	13,000	K	X=0.269(±0.002) Y=0.273(±0.002)	<Test Signal> Inner pattern (204 gray,80 IRE)
Medium	9,300	K	X=0.285(±0.002) Y=0.293(±0.002)	
Warm	6,500	K	X=0.313(±0.002) Y=0.329(±0.002)	

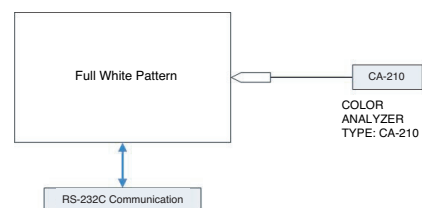
- Edge LED W/B Table in process of aging time(Only LGD Edge LED Module except AUO, CMI, IPS Module)
 CA210 : CH14, Test signal : Inner patter (80 IRE)

GP2R	Aging Time (Min.)	Cool		Medium		Warm	
		X	Y	X	Y	X	Y
		269	273	285	293	313	329
1	0-2	279	288	295	308	319	338
2	3-5	278	286	294	306	318	336
3	6-9	277	285	293	305	317	335
4	10-19	276	283	292	303	316	333
5	20-35	274	280	290	300	314	330
6	36-49	272	277	288	297	312	327
7	50-79	271	275	287	295	311	325
8	80-149	270	274	286	294	310	324
9	Over 150	269	273	285	293	309	323

*** Connecting picture of the measuring instrument**

(On Automatic control)

Inside PATTERN is used when W/B is controlled. Connect to auto controller or push Adjustment R/C POWER ON -> Enter the mode of White-Balance, the pattern will come out



* Auto-control interface and directions

- 1) Adjust in the place where the influx of light like floodlight around is blocked. (illumination is less than 10 lux).
- 2) Adhere closely the Color Analyzer (CA210) to the module less than 10cm distance, keep it with the surface of the Module and Color Analyzer's Probe vertically.(80° ~ 100°).
- 3) Aging time
 - After aging start, keep the power on (no suspension of power supply) and heat-run over 15minutes.
 - Using 'no signal' or 'full white pattern' or the others, check the back light on.

• Auto adjustment Map(RS-232C)

RS-232C COMMAND

[CMD ID DATA]

Wb 00 00 White Balance Start
Wb 00 ff White Balance End

	RS-232C COMMAND [CMD ID DATA]			MIN	CENTER (DEFAULT)			MAX
	Cool	Mid	Warm		Cool	Mid	Warm	
R Gain	jg	Ja	jd	00	172	192	192	255
G Gain	jh	Jb	je	00	172	192	192	255
B Gain	ji	Jc	jf	00	192	192	172	255
R Cut					64	64	64	128
G Cut					64	64	64	128
B Cut					64	64	64	128

** Caution **

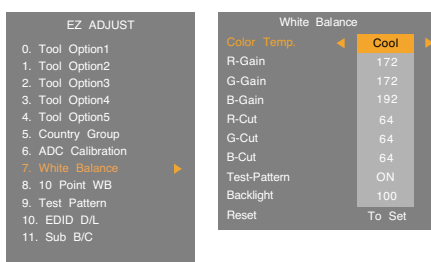
Color Temperature : COOL, Medium, Warm.

One of R Gain/G Gain/ B Gain should be kept on 0xC0, and adjust other two lower than C0.

(when R/G/B Gain are all C0, it is the FULL Dynamic Range of Module)

* Manual W/B process using adjusts Remote control.

- After enter Service Mode by pushing "ADJ" key,
- Enter White Balance by pushing "►" key at "7. White Balance".



- * After done all adjustments, Press "In-start" key and compare Tool option and Area value with its BOM, if it is correctly same then unplug the AC cable. If it is not same, then correct it same with BOM and unplug AC cable. For correct it to the model's module from factory Jig model.
- * Push the "IN STOP" key after completing the function inspection. And Mechanical Power Switch must be set "ON".

4.2. DDC EDID Write (RGB 128Byte)

- Connect D-sub Signal Cable to D-sub Jack.
- Write EDID Data to EEPROM(24C02) by using DDC2B protocol.
- Check whether written EDID data is correct or not.
- * For Service main Assembly, EDID have to be downloaded to Insert Process in advance.

4.3. DDC EDID Write (HDMI 256Byte)

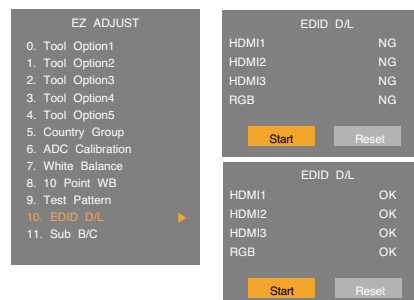
- Connect HDMI Signal Cable to HDMI Jack.
- Write EDID Data to EEPROM(24C02) by using DDC2B protocol.
- Check whether written EDID data is correct or not.
- * For Service main Assembly, EDID have to be downloaded to Insert Process in advance.

4.4. EDID DATA

- 1) All Data : HEXA Value
- 2) Changeable Data :
 - *: Serial No : Controlled / Data:01
 - ** : Month : Controlled / Data:00
 - ***: Year : Controlled
 - ****: Check sum

- Auto Download

- Enter 'EZ ADJUST' mode by pushing 'ADJ' key,
 - Enter EDID D/L mode.
 - Enter 'START' by pushing 'OK' key.
- <Caution> Never connect HDMI & D-sub cable when EDID download






* EDID data and Model option download (RS232)

NO	Item	CMD1	CMD2	Data0	
Enter download Mode	Download 'Mode In'	A	A	0 0	When transfer the 'Mode In', Carry the command.
EDID data and Model option download	Download	A	E	00 10	Automatically Download (The use of a internal pattern)

- Manual Download

* Caution

- 1) Use the proper signal cable for EDID Download
 - Analog EDID : Pin3 exists
 - Digital EDID : Pin3 exists
- 2) Never connect HDMI & D-sub Cable at the same time.
- 3) Use the proper cables below for EDID Writing.
- 4) Download HDMI1, HDMI2, separately because HDMI1 is different from HDMI2.

For Analog EDID	For HDMI EDID	
D-sub to D-sub	DVI-D to HDMI or HDMI to HDMI	
		

Item	Condition	Data(Hex)
Manufacturer ID	GSM	1E6D
Version	Digital : 1	01
Revision	Digital : 3	03

(1) FHD RGB EDID DATA

	0	1	2	3	4	5	6	7	8	9	A	B	C	D	E	F
0	0	ff	ff	ff	ff	ff	ff	0	1e	6d	a		b			
10	c		1	3	68	10	9	78	0a	ee	91	a3	54	4c	99	26
20	0f	50	54	a1	8	0	81	80	61	40	45	40	31	40	1	1
30	1	1	1	1	1	1	2	3a	80	18	71	38	2d	40	58	2c
40	45	0	a0	5a	0	0	0	1e	1	1d	0	72	51	d0	1e	20
50	6e	28	55	0	a0	5a	0	0	0	1e	0	0	0	fd	0	3a
60	3e	1e	53	10	0	0a	20	20	20	20	20	20	d			
70	d														0	e

(2) FHD HDMI EDID DATA

	0	1	2	3	4	5	6	7	8	9	A	B	C	D	E	F
0	0	ff	ff	ff	ff	ff	ff	0	1e	6d	a		b			
10	c		1	3	80	10	9	78	0a	ee	91	a3	54	4c	99	26
20	0f	50	54	a1	8	0	71	4f	81	80	1	1	1	1	1	1
30	1	1	1	1	1	1	2	3a	80	18	71	38	2d	40	58	2c
40	45	0	a0	5a	0	0	0	1e	1b	21	50	a0	51	0	1e	30
50	48	88	35	0	a0	5a	0	0	0	1c	0	0	0	fd	0	3a
60	3e	1e	53	10	0	0a	20	20	20	20	20	20	d			
70	d														1	e
80	2	3	26	f1	4e	10	1f	84	13	5	14	3	2	12	20	21
90	22	15	1	26	15	7	50	9	57	7	f					
A0	f		e3	5	3	1	1	1d	80	18	71	1c	16	20	58	2c
B0	25	0	a0	5a	0	0	0	9e	1	1d	0	72	51	d0	1e	20
C0	6e	28	55	0	a0	5a	0	0	0	1e	2	3a	80	18	71	38
D0	2d	40	58	2c	45	0	a0	5a	0	0	0	1e	1	1d	0	bc
E0	52	d0	1e	20	b8	28	55	40	a0	5a	0	0	0	1e	0	0
F0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	e

(3) Detail EDID Options are below

a. Product ID

Model Name	HEX	EDID Table	DDC Function
HD/FHD Model	0001	01 00	Analog/Digital

b. Serial No: Controlled on production line.

c. Month, Year:

Week : '01' -> '01'

Year : '2011' -> '15' fix

d. Model Name(Hex):

MODEL	MODEL NAME(HEX)
LG TV	00 00 00 FC 00 4C 47 20 54 56 0A 20 20 20 20 20 20

e. Checksum: Changeable by total EDID data.

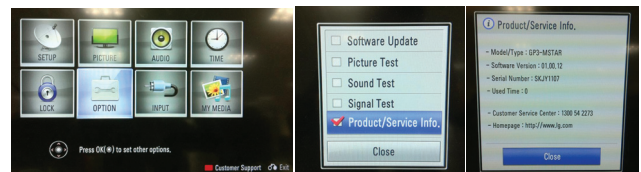
EDID C/S data		FHD		SMALL FHD		HD	
		HDMI	RGB	HDMI	RGB	HDMI	RGB
Check sum (Hex)	Block 0	E2	1C	E2	ED	B4	CD
	Block 1	99(HDMI1)		5F(HDMI1)		75(HDMI1)	
		89(HDMI2)		4F(HDMI2)		65(HDMI2)	
		79(HDMI3)		3F(HDMI3)		55(HDMI3)	

f. Vendor Specific(HDMI)

INPUT	MODEL NAME(HEX)
HDMI1	67030C001000B82D
HDMI2	67030C002000B82D
HDMI3	67030C003000B82D

4.5. Model name & Serial number download

- Press "Power on" key of service remote control.
(Baud rate : 115200 bps)
- Connect RS232 Signal Cable to RS-232 Jack.
- Write Serial number by use RS-232.
- Must check the serial number at the Product/Service info.(menu key -> red key -> select product/Service info.)



4.5.1. Signal TABLE

CMD	LENGTH	ADH	ADL	DATA_1	...	Data_n	CS	DELAY
-----	--------	-----	-----	--------	-----	--------	----	-------

CMD : A0h

LENGTH : 85~94h (1~16 bytes)

ADH : EEPROM Sub Address high (00~1F)

ADL : EEPROM Sub Address low (00~FF)

Data : Write data

CS : CMD + LENGTH + ADH + ADL + Data_1 +...+ Data_n

Delay : 20ms

4.5.2. Command Set

No.	Adjust mode	CMD(hex)	LENGTH(hex)	Description
1	EEPROM WRITE	A0h	84h+n	n-bytes Write(n=1~16)

* Description

FOS Default write : <7mode data> write

Vtotal, V_Frequency, Sync_Polarity, Htotal, Hstart, Vstart, 0, Phase

Data write: Model name and Serial number write in EEPROM,.

4.5.3. Method & notice

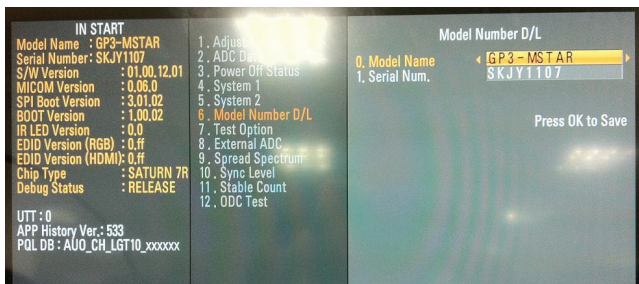
- Serial number D/L is using of scan equipment.
- Setting of scan equipment operated by Manufacturing Technology Group.
- Serial number D/L must be conformed when it is produced in production line, because serial number D/L is mandatory by D-book 4.0.

* Manual Download (Model Name and Serial Number)

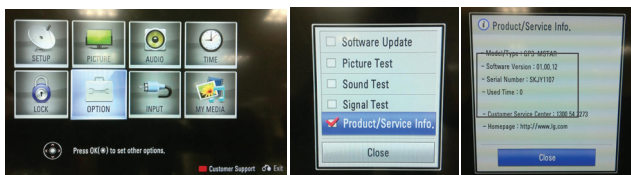
If the TV set is downloaded by OTA or Service man, sometimes model name or serial number is initialized.(Not always)

There is impossible to download by bar code scan, so It need Manual download.

- Press the 'Instart' key of Adjustment remote control.
- Go to the menu '6.Model Number D/L' like below photo.
- Input the Factory model name(ex 32LV2510-TB) or Serial number like photo.



- Check the model name Instart menu. -> Factory name displayed. (ex 32LV2510-TB)
- Check the Diagnostics. (DTV country only) -> Buyer model displayed. (ex 32LV2510)



4.5.4. Outgoing condition Configuration

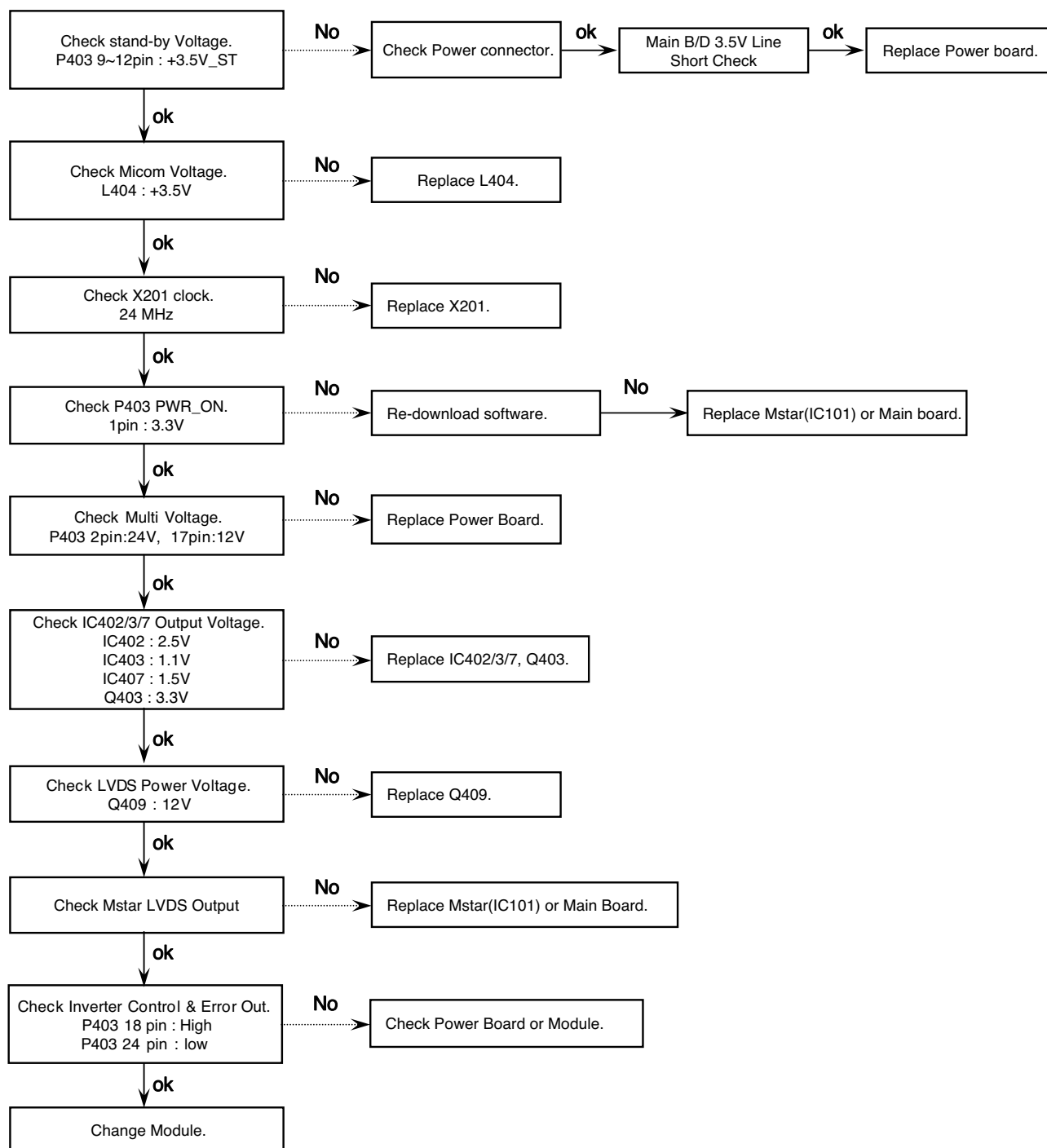
- When pressing IN-STOP key by Service remote control, Red LED are blinked alternatively. And then automatically turn off. (Must not AC power OFF during blinking)

4.6. Hi-pot test

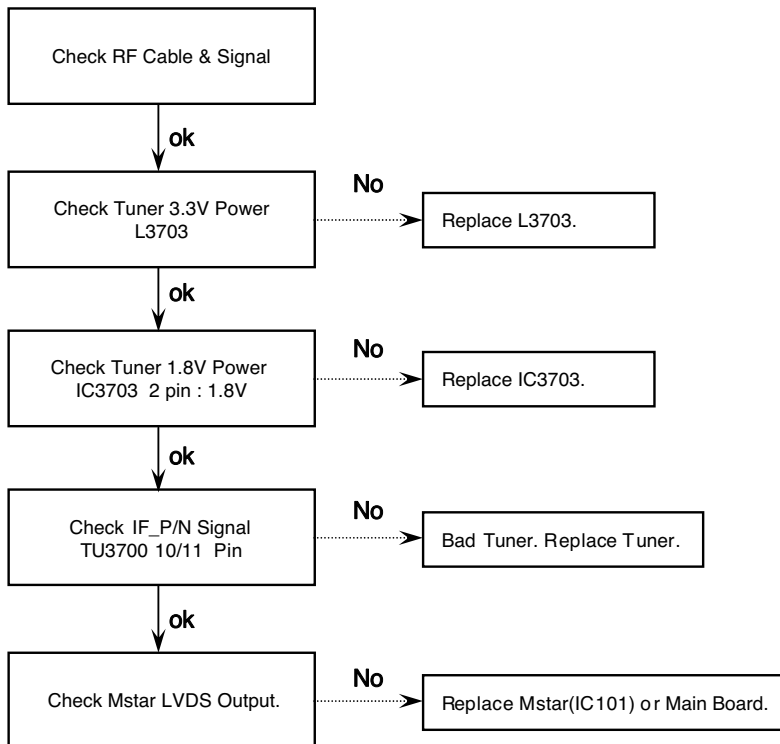
Confirm whether is normal or not when between power board's ac block and GND is impacted on 1.5 kV(dc) or 2.2 kV(dc) for one second.

TROUBLESHOOTING

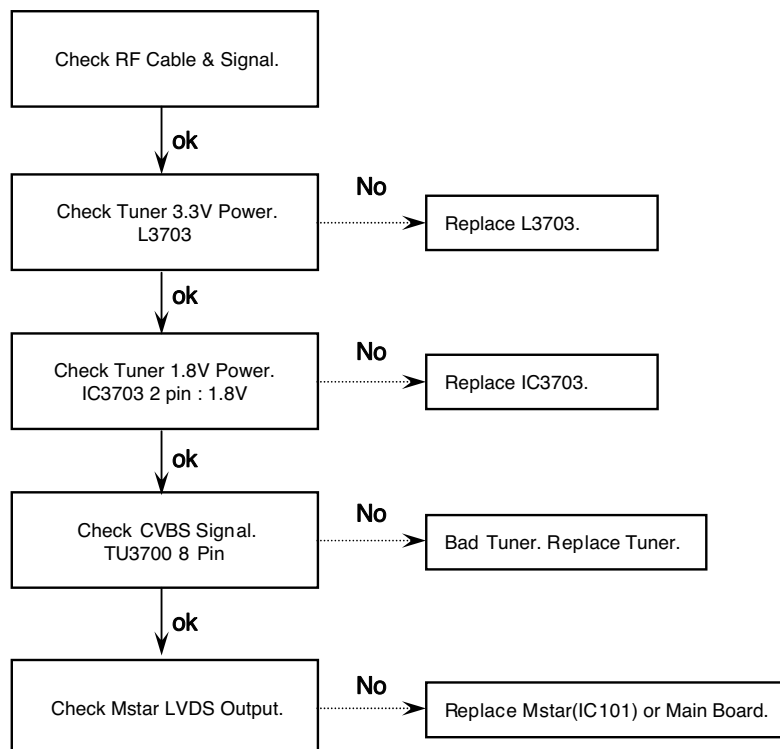
1. Power-up boot check



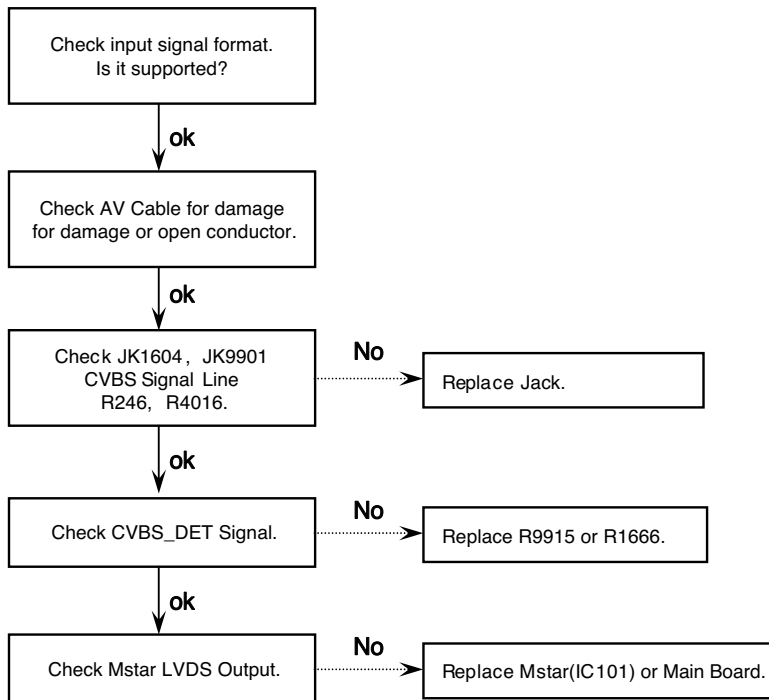
2. Digital TV Video



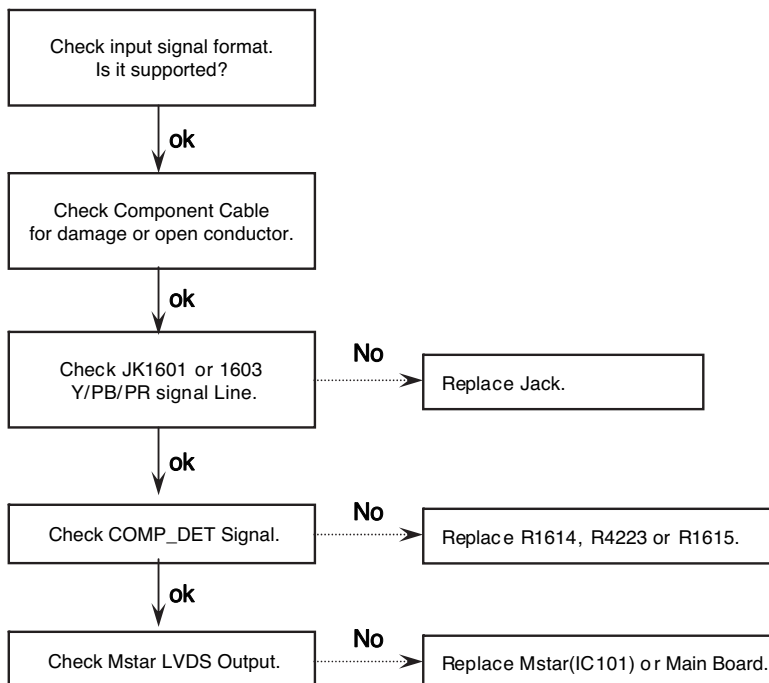
3. Analog TV Video



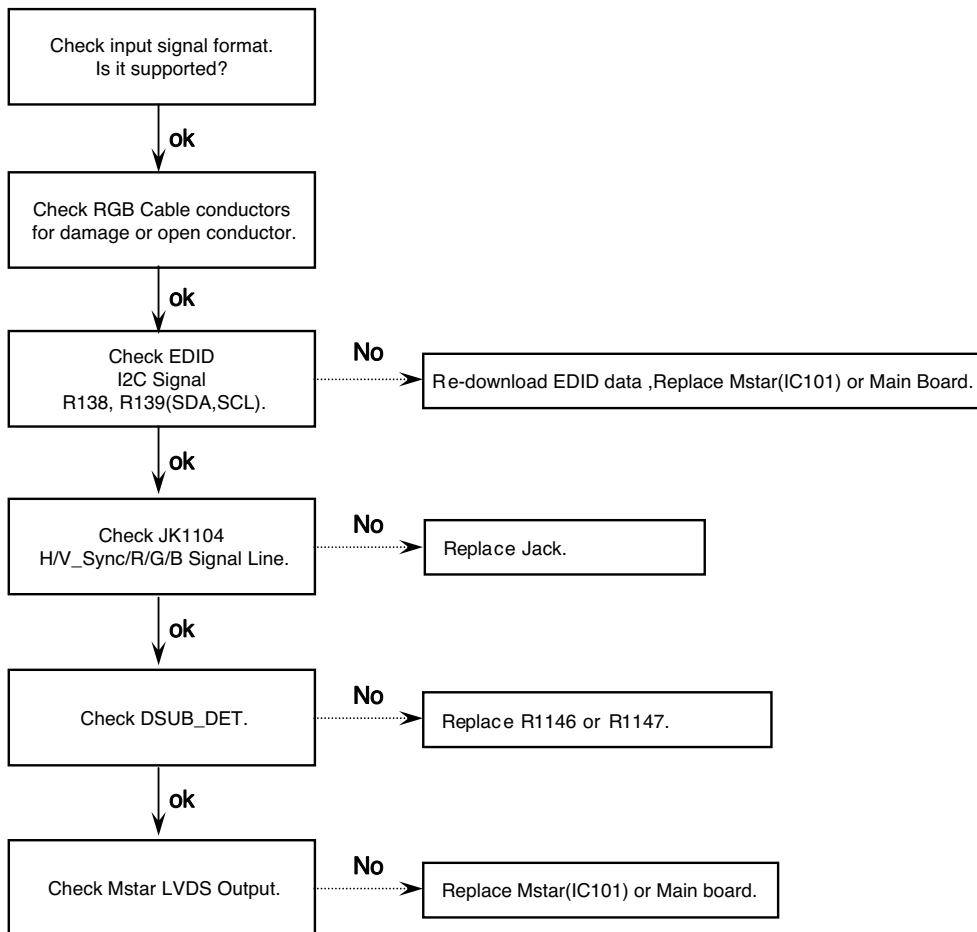
4. AV Video



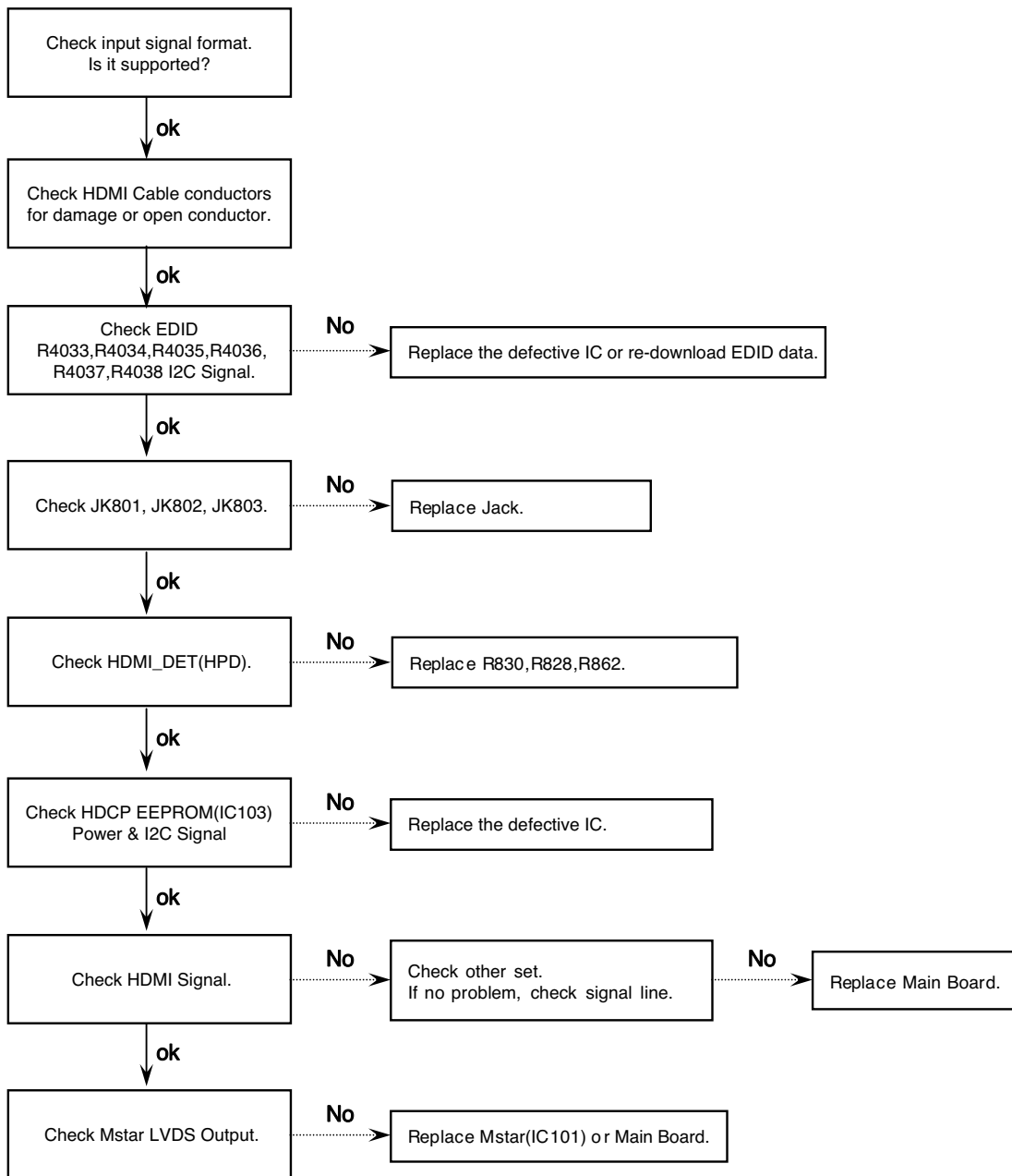
5. Component Video



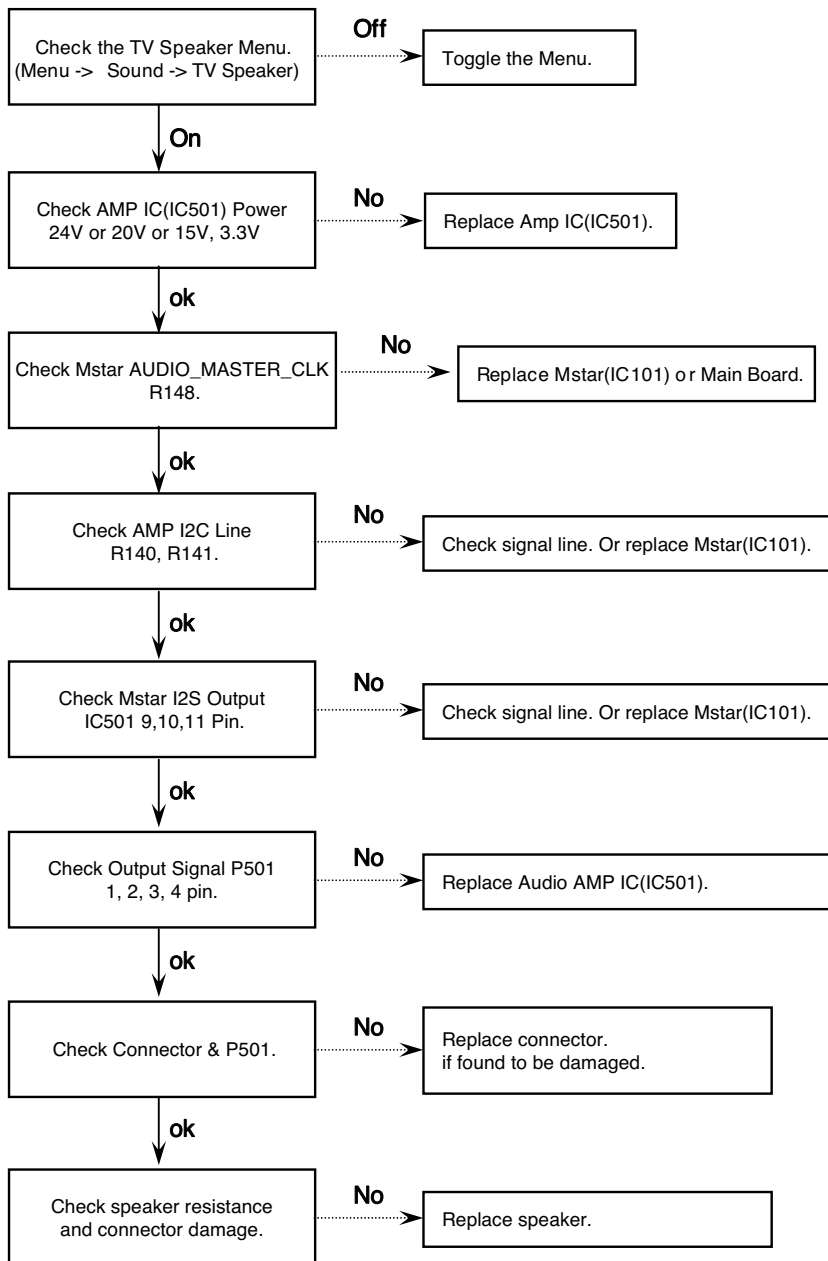
6. RGB Video



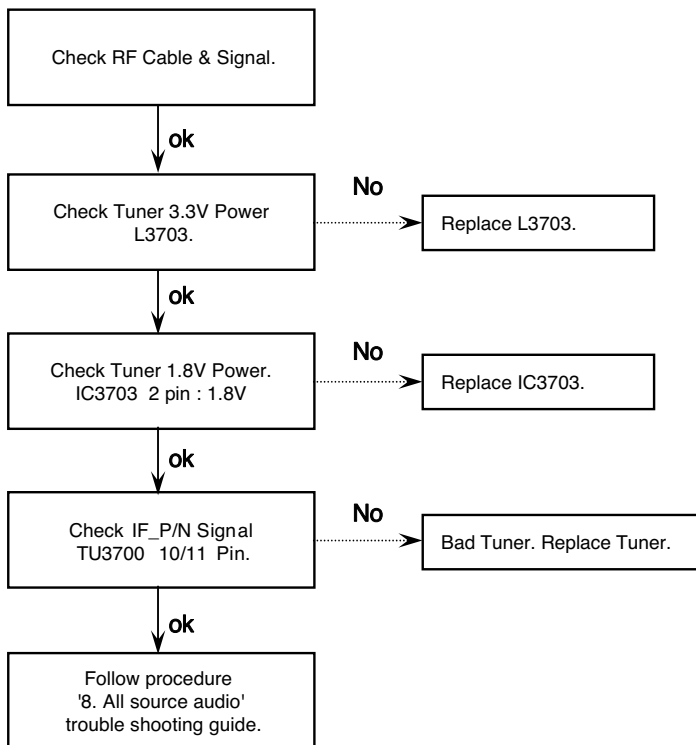
7. HDMI Video



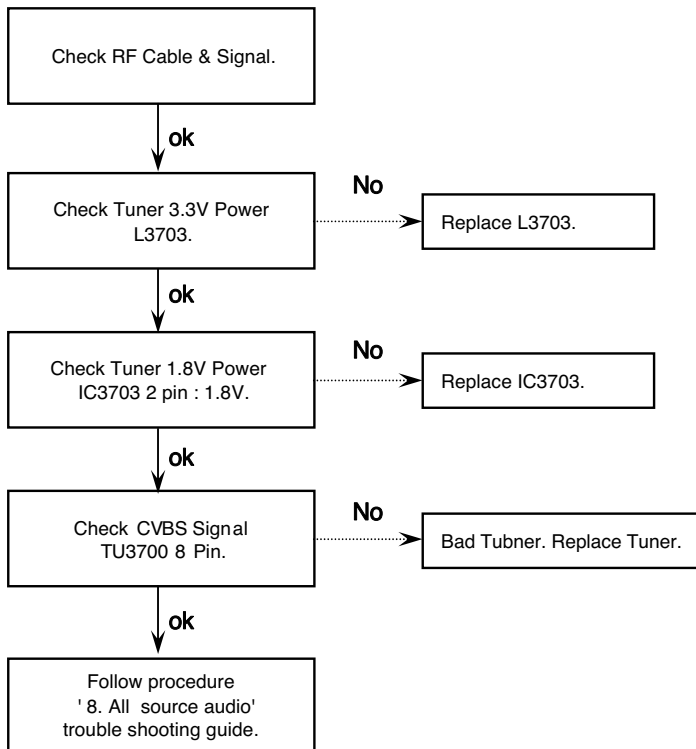
8. All Source Audio



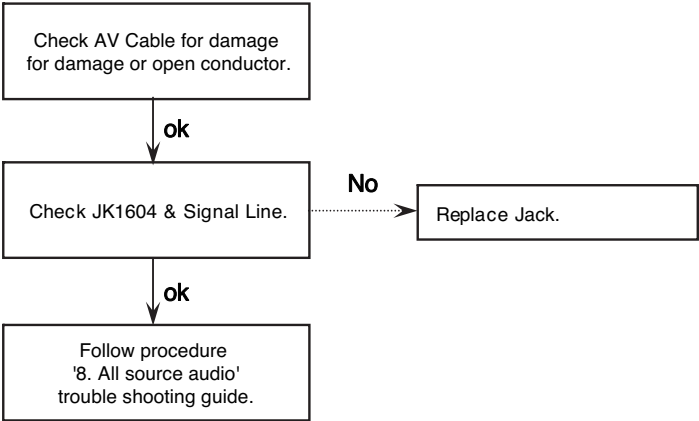
9. Digital TV Audio



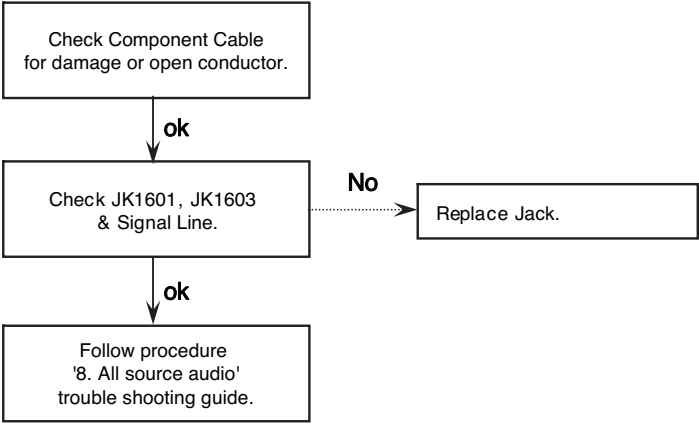
10. Analog TV Audio



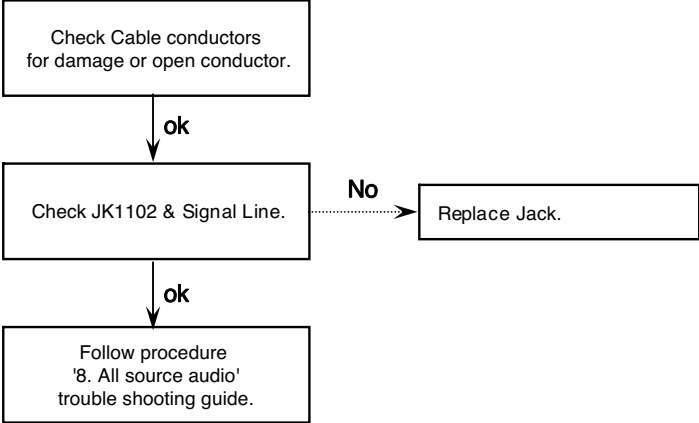
11. AV Audio



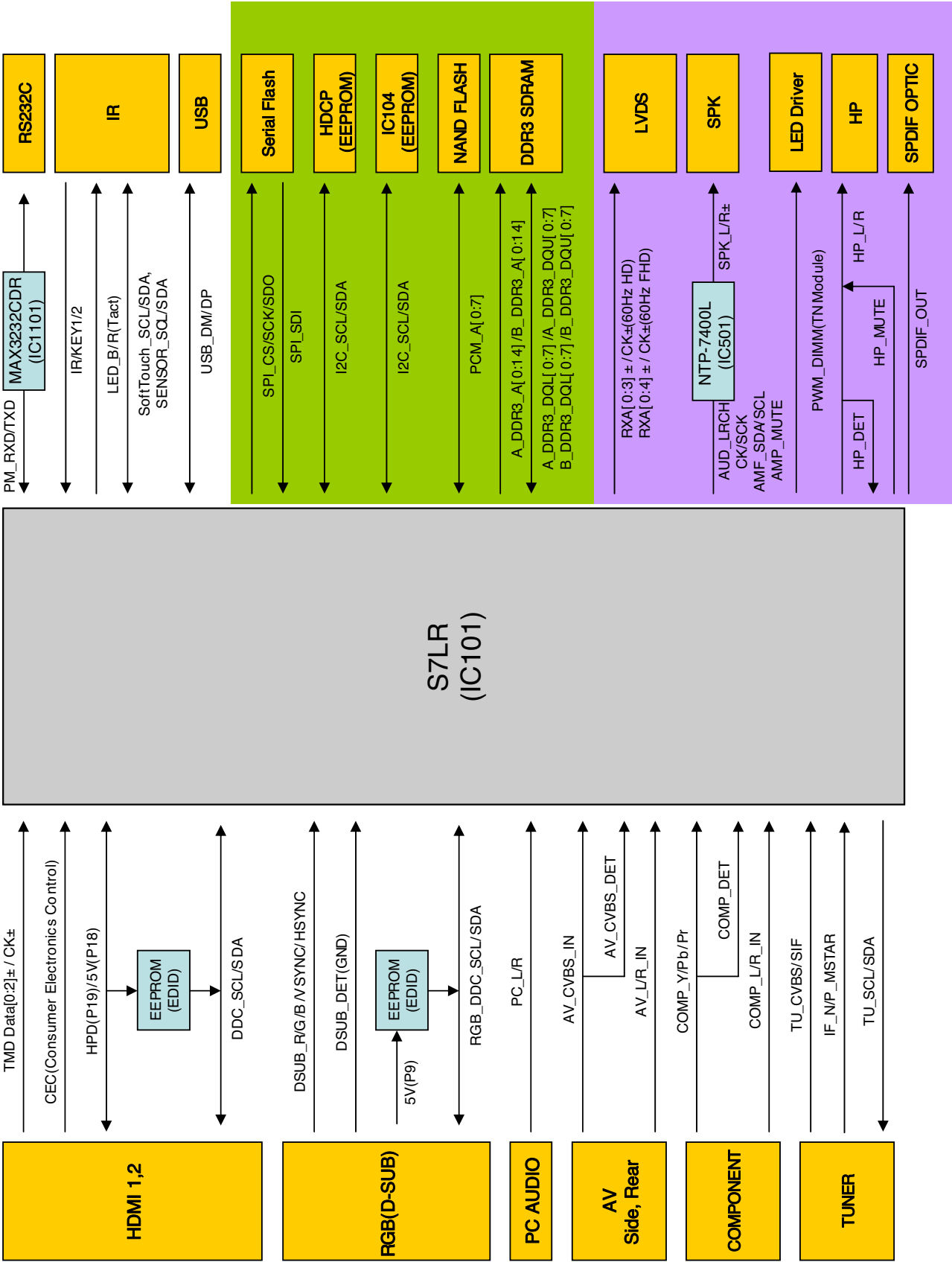
12. Component Audio



13. RGB Audio



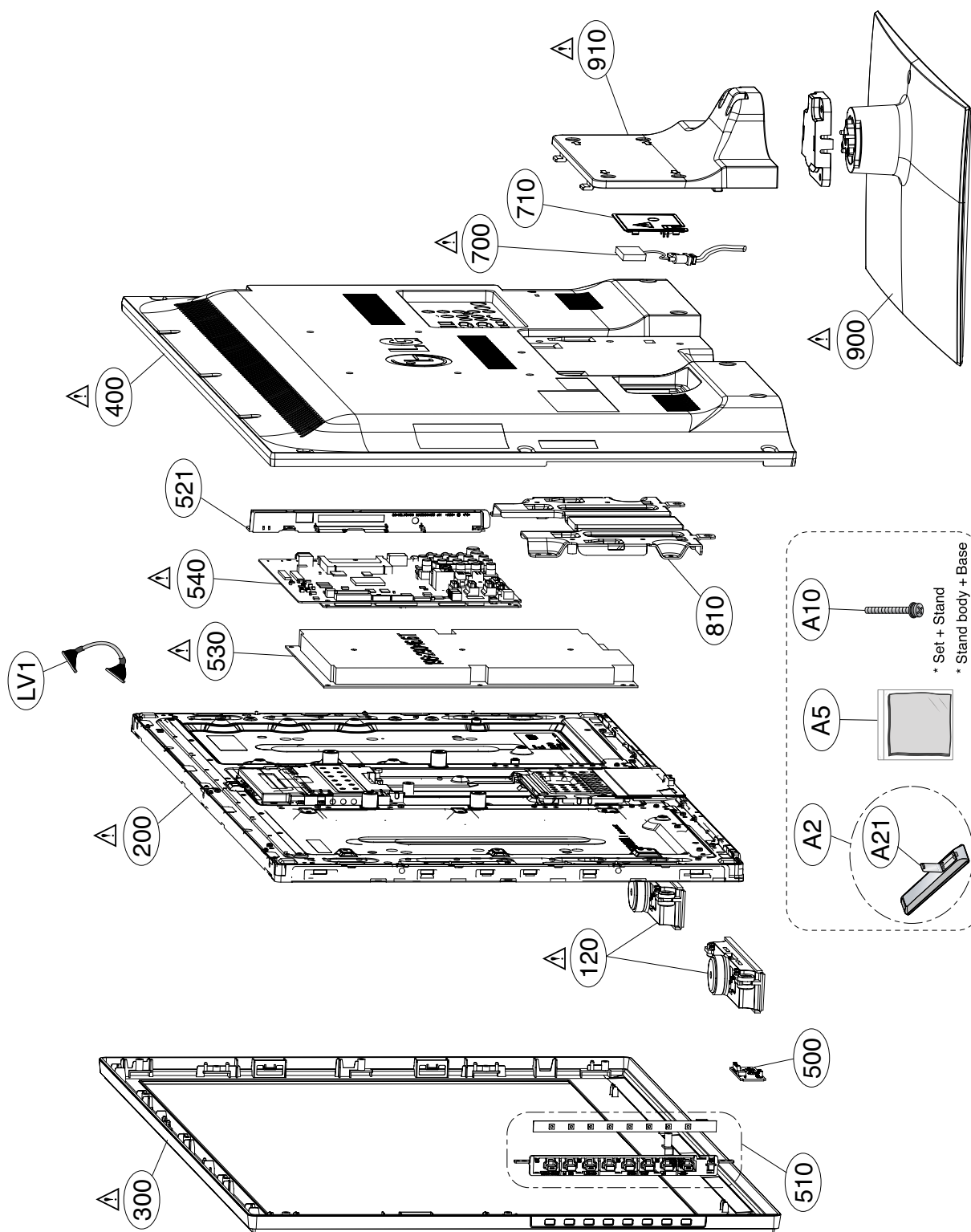
BLOCK DIAGRAM

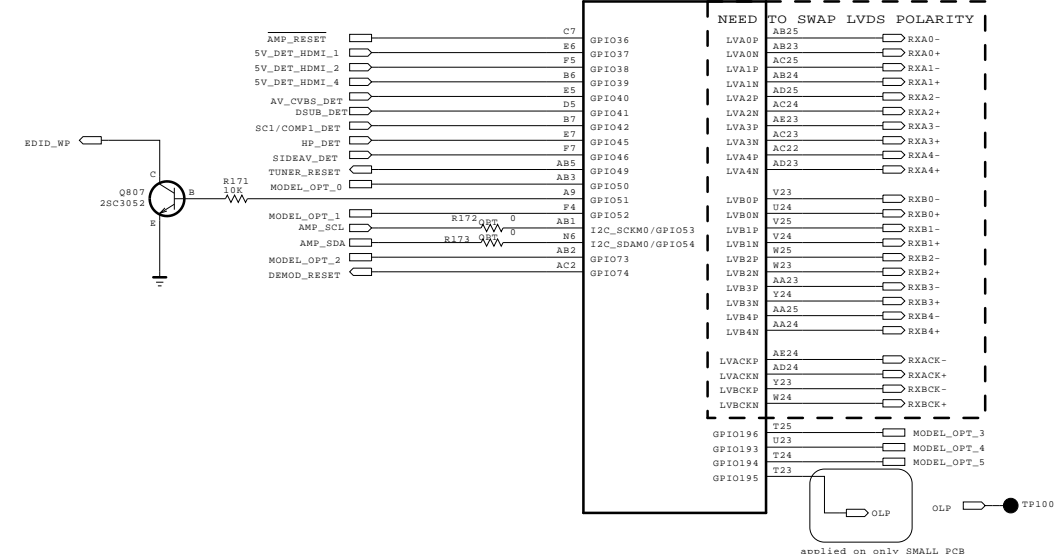
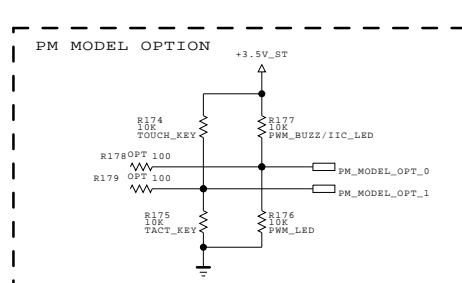
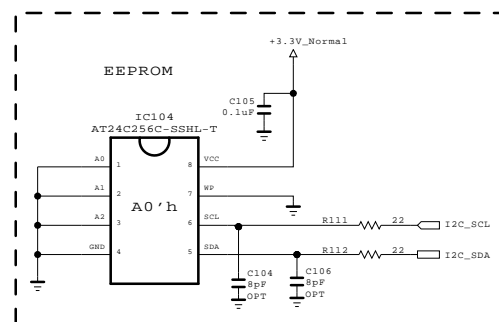
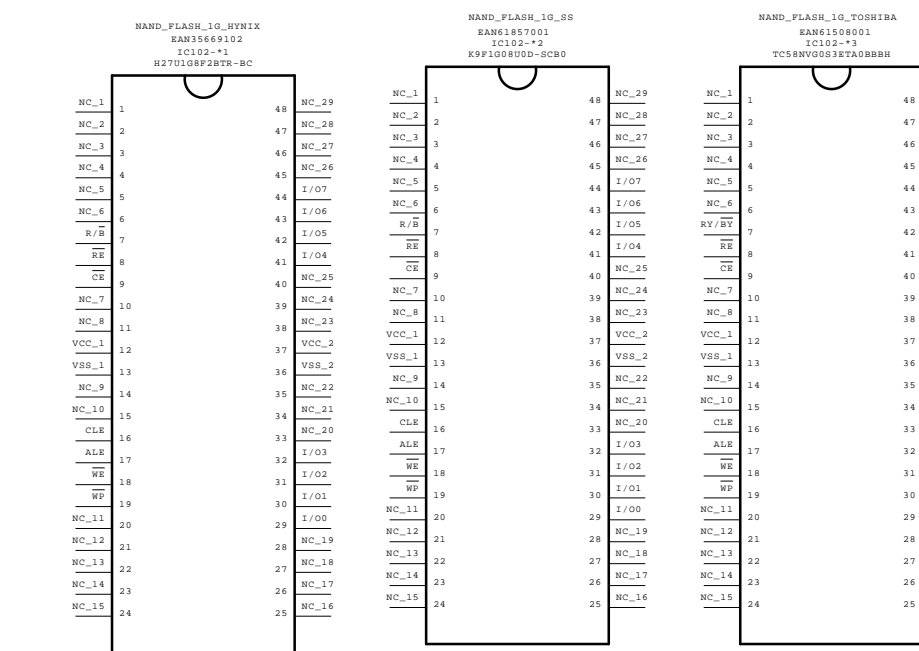
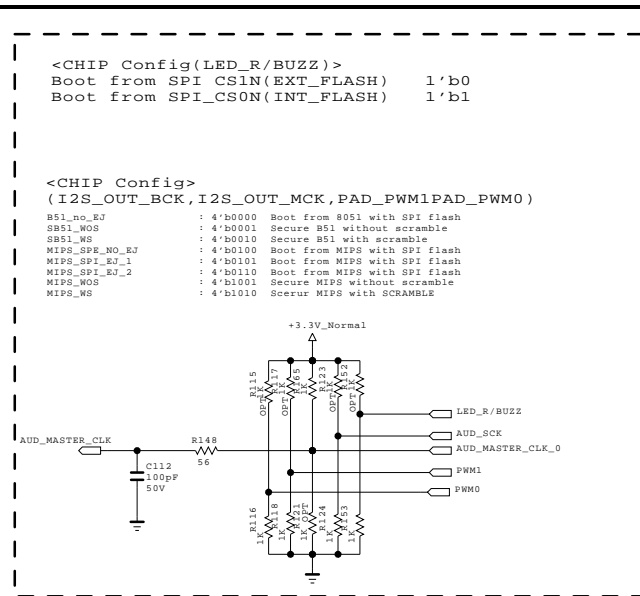


EXPLODED VIEW

IMPORTANT SAFETY NOTICE

Many electrical and mechanical parts in this chassis have special safety-related characteristics. These parts are identified by Δ in the Schematic Diagram and EXPLODED VIEW. It is essential that these special safety parts should be replaced with the same components as recommended in this manual to prevent X-RADIATION, Shock, Fire, or other Hazards. Do not modify the original design without permission of manufacturer.

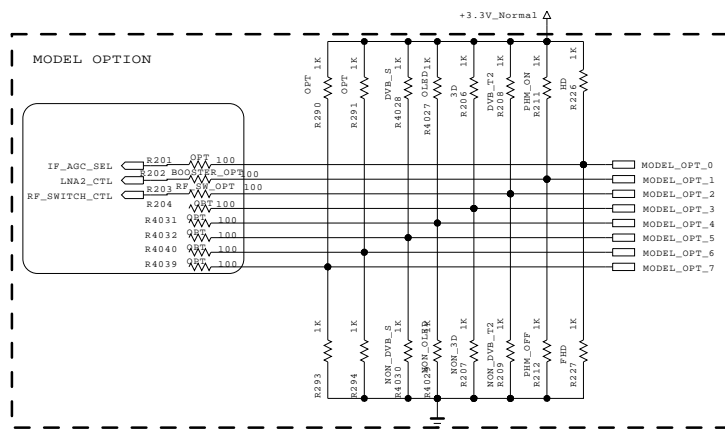




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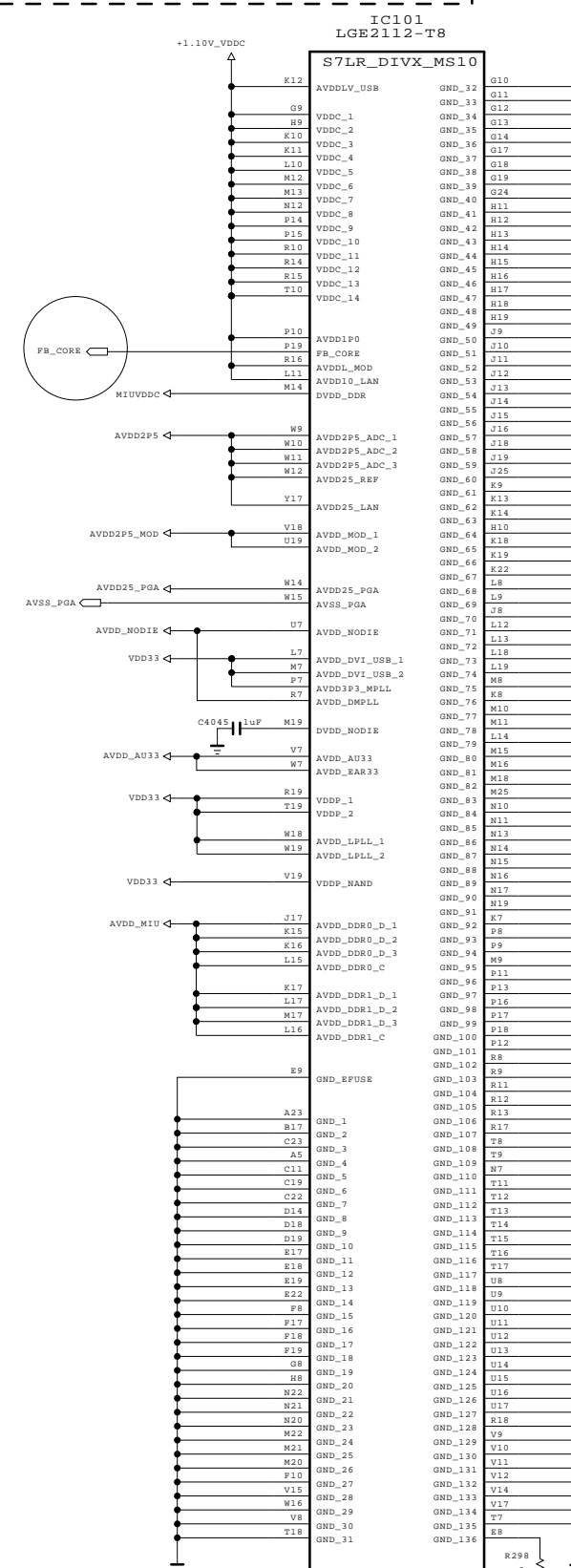
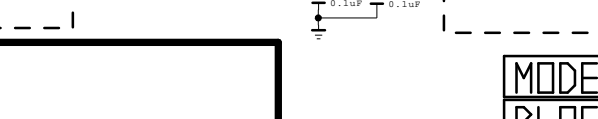
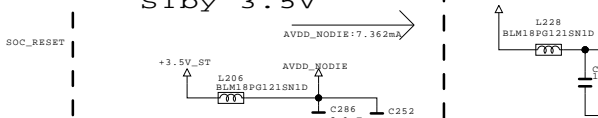
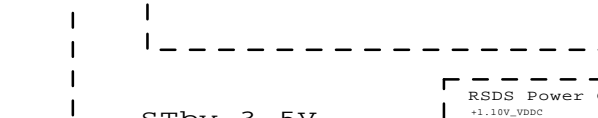
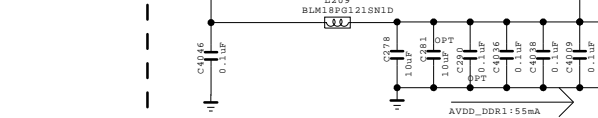
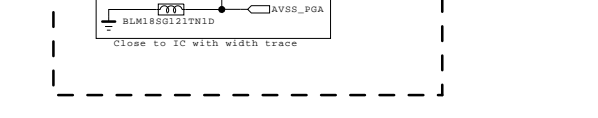
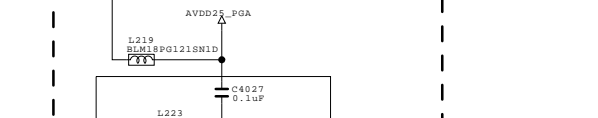
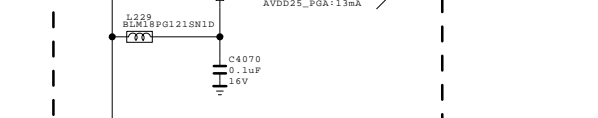
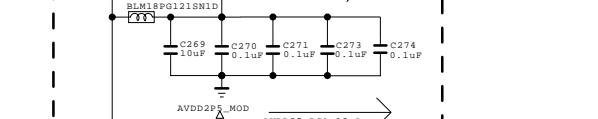
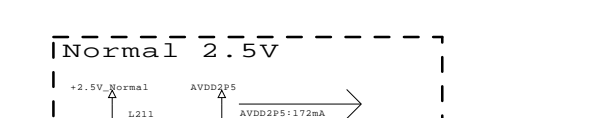
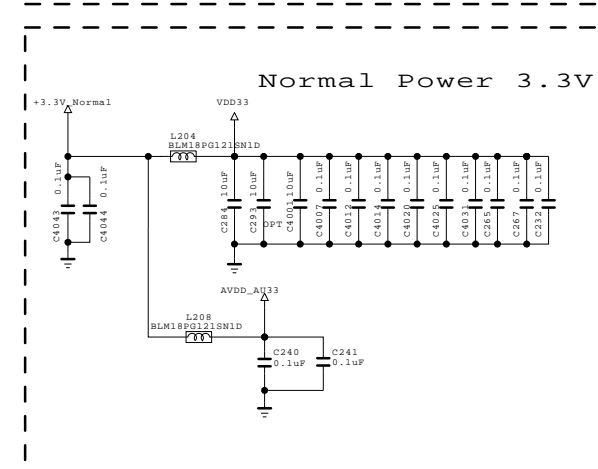
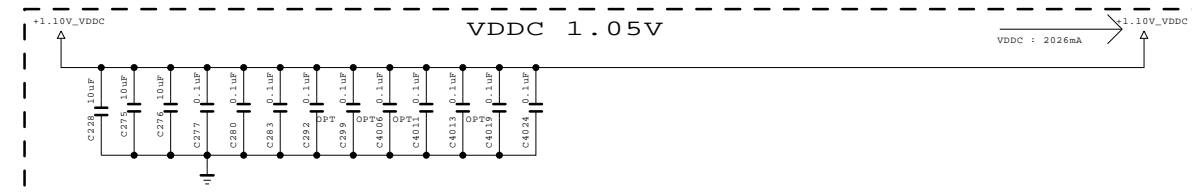
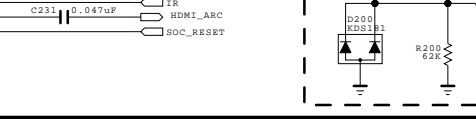
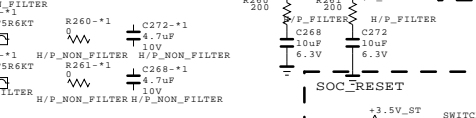
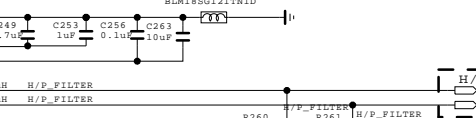
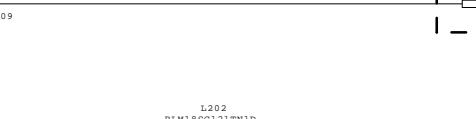
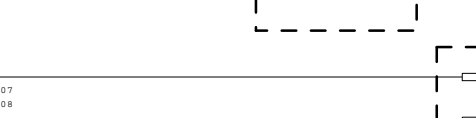
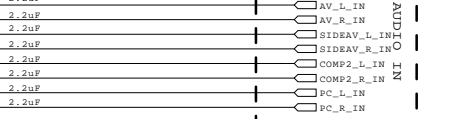
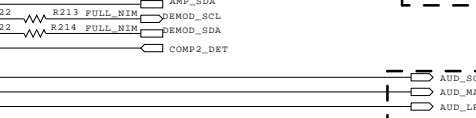
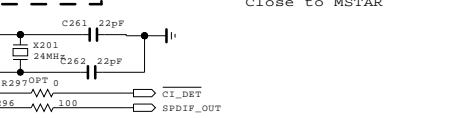
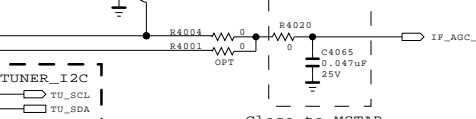
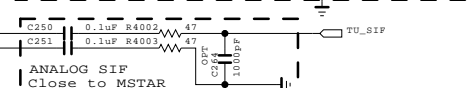
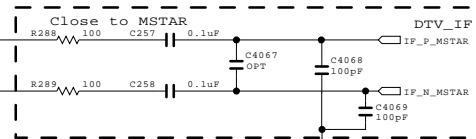


MODEL	GP3_S7LR	DATE	20110511
BLOCK	FLASH/EEPROM/GPIO	SHEET	1 /



MODEL OPTION			
PIN NAME	PIN NO.	LOW	HIGH
MODEL_OPT_0	AB3	FHD	HD
MODEL_OPT_1	F4	PHM_OFF	PHM_ON
MODEL_OPT_2	AB2	NON_DVB_T2	DVB_T2
MODEL_OPT_3	T25	NON_3D	3D
MODEL_OPT_4	U23	NON_OLED	OLED
MODEL_OPT_5	T24	NON_DVB_S	DVB_S
MODEL_OPT_6	B8	READY	READY
MODEL_OPT_7	A8	READY	READY

IC101
LGE2112-T8



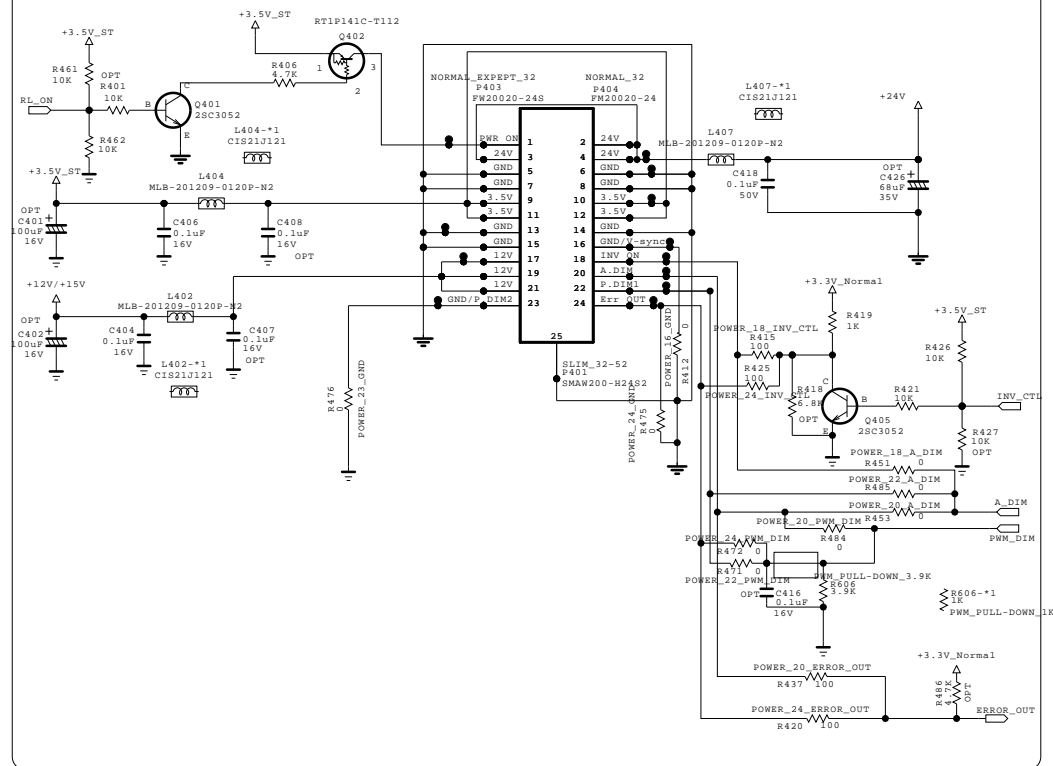
THE SYMBOL MARK OF THIS SCHEMATIC DIAGRAM INCORPORATES SPECIAL FEATURES IMPORTANT FOR PROTECTION FROM X-RADIATION. FILTRE AND ELECTRICAL SHOCK HAZARDS, WHEN SERVICING IF IS ESSENTIAL THAT ONLY MANUFACTURES SPECIFIED PARTS BE USED FOR THE CRITICAL COMPONENTS IN THE SYMBOL MARK OF THE SCHEMATIC.

SECRET
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MODEL	GP3_S7LR	DATE	20110511
BLOCK	MAIN2, HW OPT	SHEET	2

FROM LIPS & POWER B/D



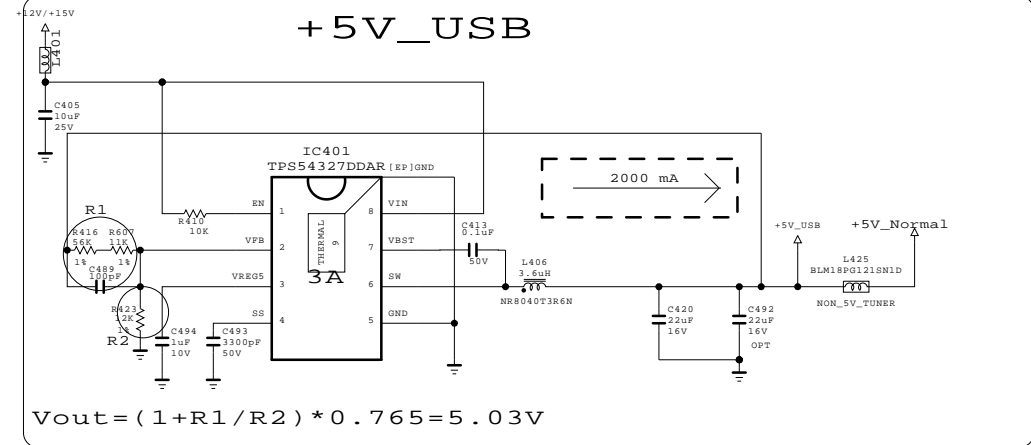
<MODULE PIN MAP>

PIN No	LGD (PSU) or LIPS	CHO10*Lamp (PSU)	AUO 10*Lamp (PSU)	SHARP (PSU)	IPS-@ (PSU)
16	GND	GND	GND	GND	GND
18	INV_ON	A-DIM	INV_ON	INV_ON	INV_ON
20	VBR-A	NC	Err_out	52/60:ERROR 26/32HD:NC	Err_out
22	PWM_DIM	PWM_DIM	NC	26/32/52:PWM 60:NC	NC
24	Err_out	INV_ON	PWM_DIM	26/32/52:GND 60:PWM	PWM_DIM
23	GND	GND	GND	GND	GND

<LED MODULE PIN MAP -> latest update 20100618>

PIN No	LGD LPB/ OS LPB	32LKS300-TA CHO10*LED (PSU)	32LKS300-TA AUO 10*LED (PSU)	32LKS300-TA LGD 10*LED (PSU)
16	NC	NC	NC	NC
18	INV_ON	INV_ON	INV_ON	INV_ON
20	NC	err_out -> NC	err_out -> NC	NC
22	PWM_DIM	NC	NC	PWM_DIM
24	err_out -> NC	PWM_DIM	PWM_DIM	err_out -> NC
23	NC	NC	NC	NC

LGD edge led error-out use or not? checking is necessary...

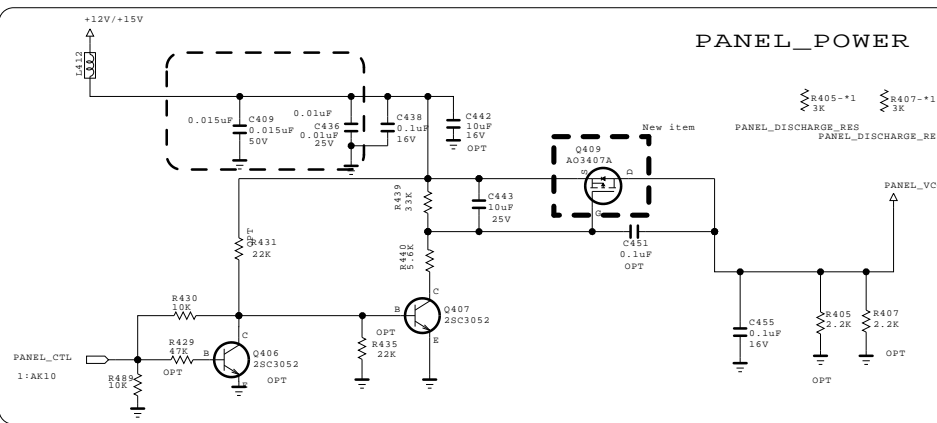


THE SYMBOL MARK OF THIS SCHEMATIC DIAGRAM INCORPORATES SPECIAL FEATURES IMPORTANT FOR PROTECTION FROM X-RADIATION. FILRE AND ELECTRICAL SHOCK HAZARDS, WHEN SERVICING IF IS ESSENTIAL THAT ONLY MANUFACTURES SPECIFIED PARTS BE USED FOR THE CRITICAL COMPONENTS IN THE SYMBOL MARK OF THE SCHEMATIC.

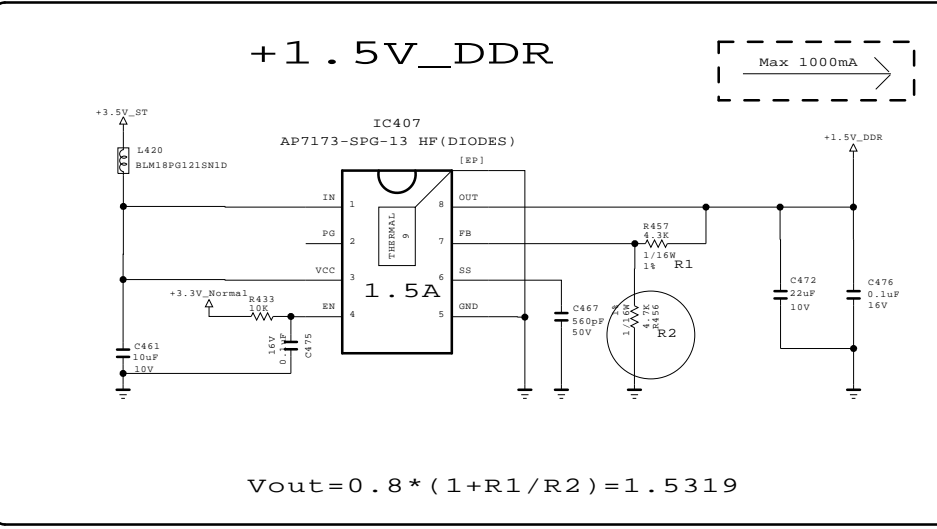
SECRET
LGElectronics

LG ELECTRONICS

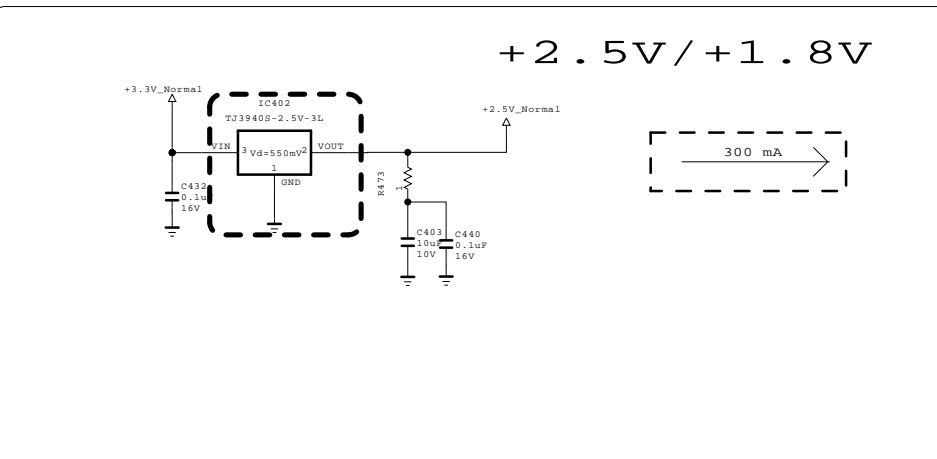
PANEL_POWER



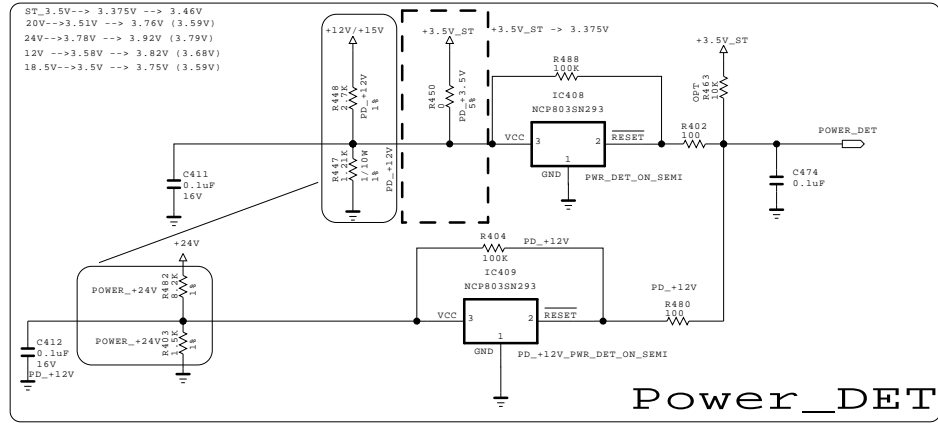
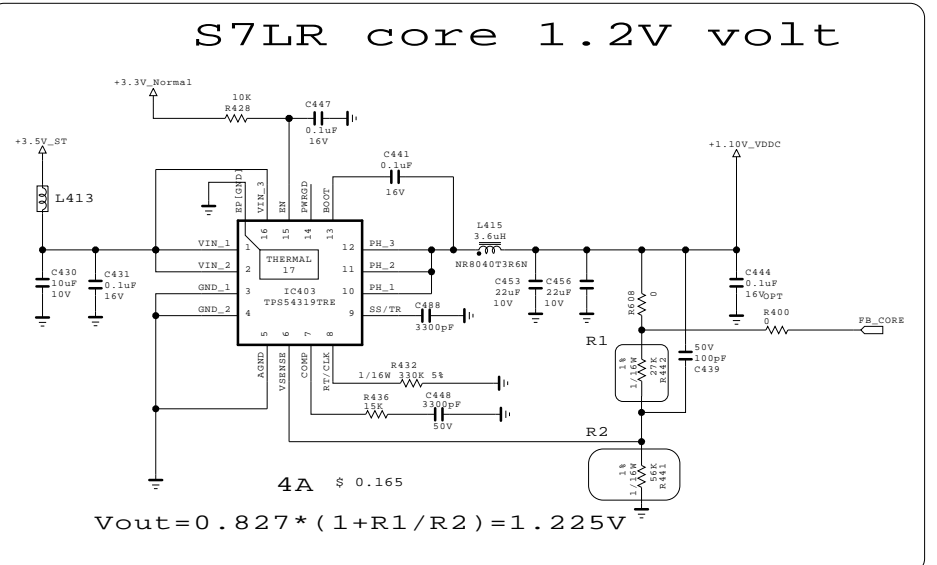
+1.5V_DDR



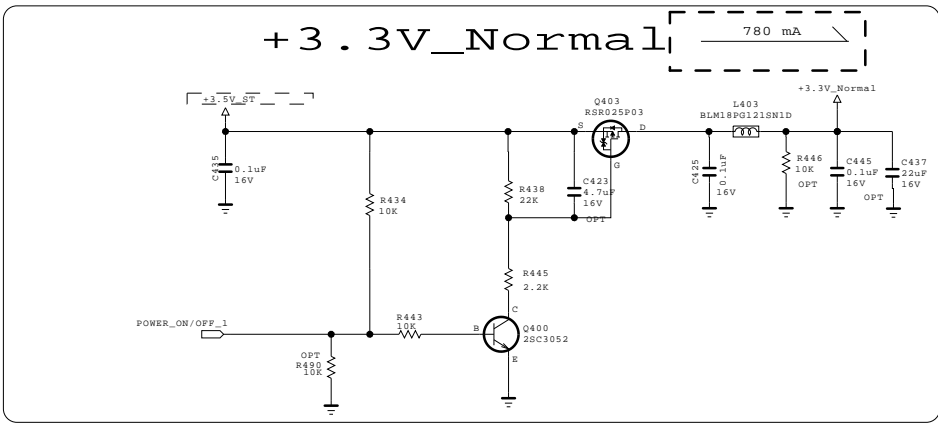
+2.5V/+1.8V



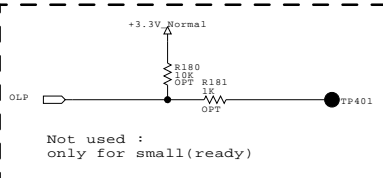
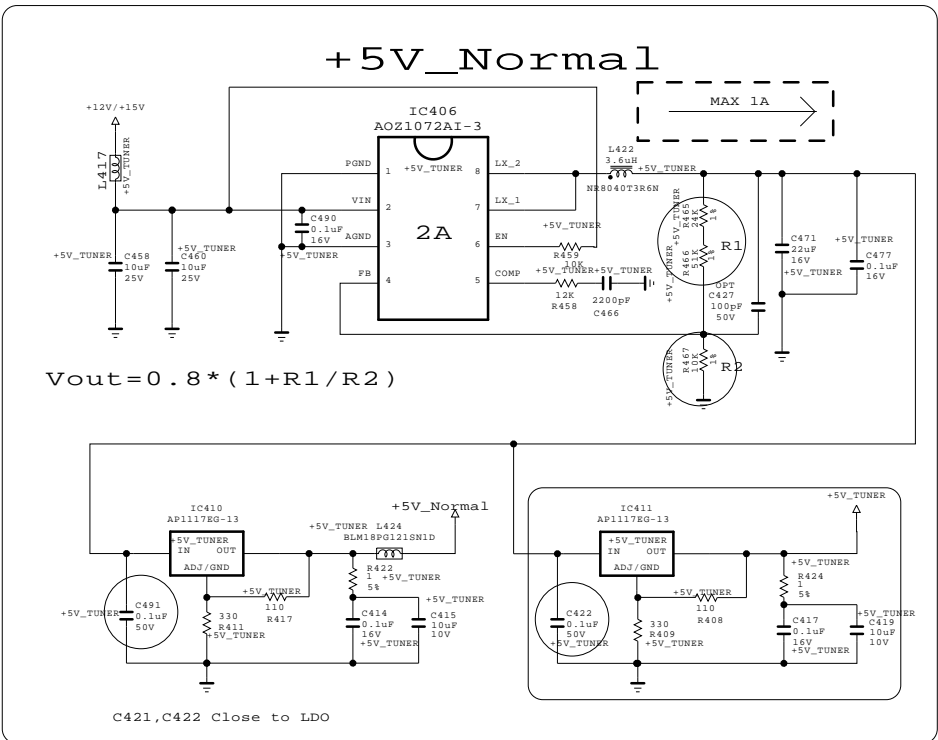
S7LR core 1.2V volt



+3.3V_Normal

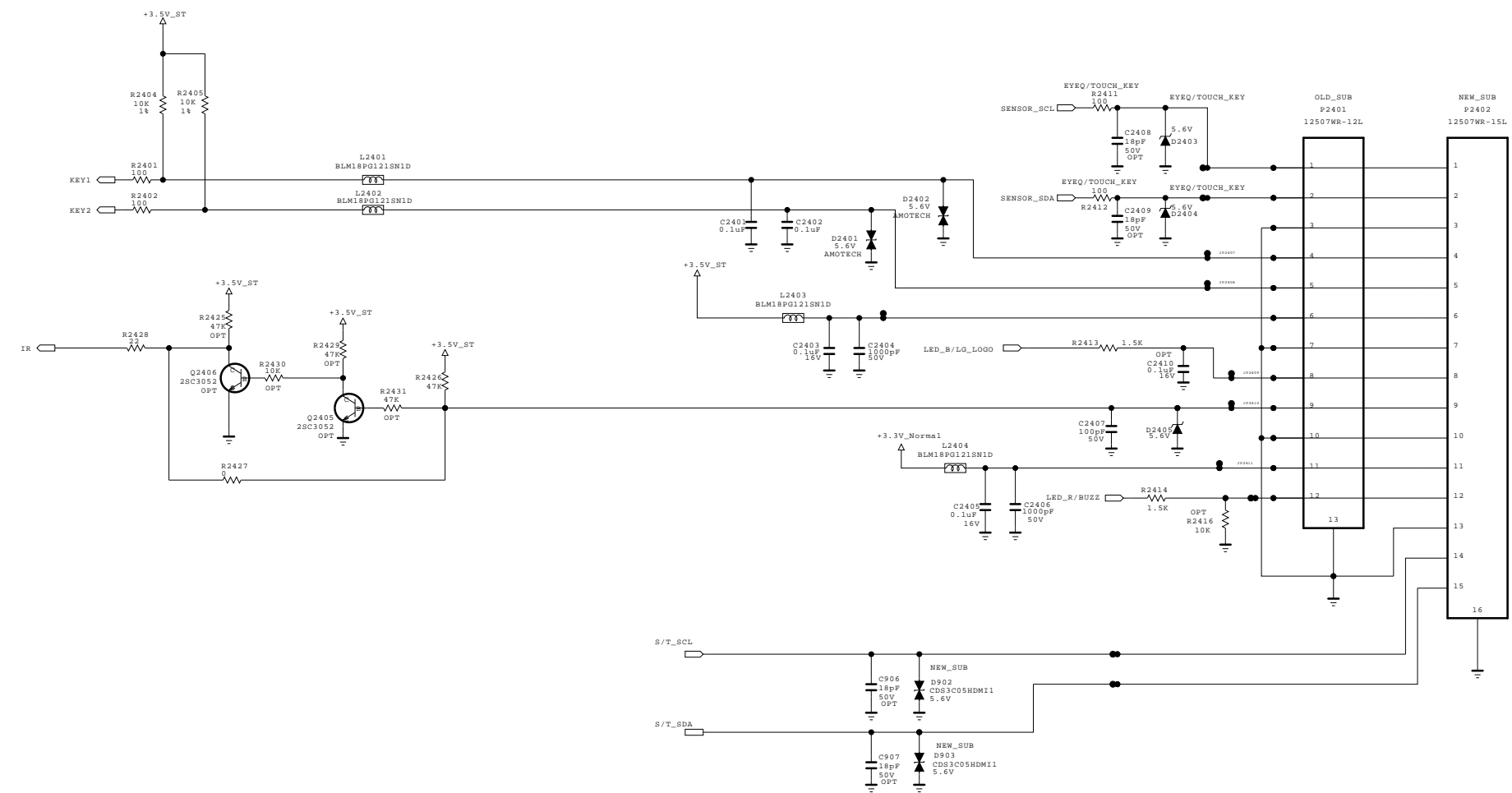




+5V_Normal



MODEL	GP3_S7LR	DATE	20110324
BLOCK	POWER_LARGE	SHEET	4

CONTROL
IR & LED

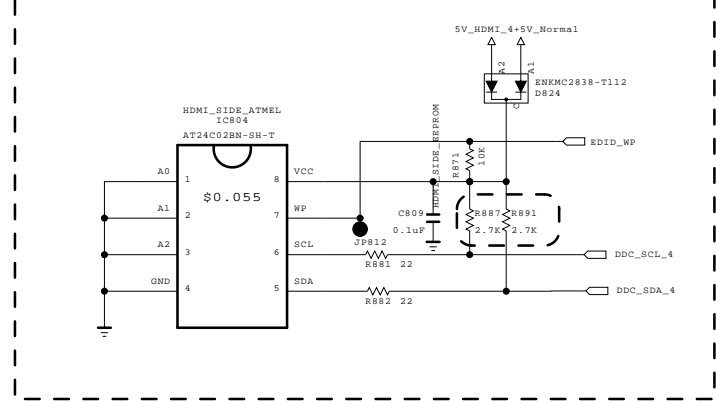
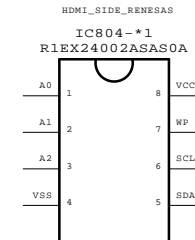
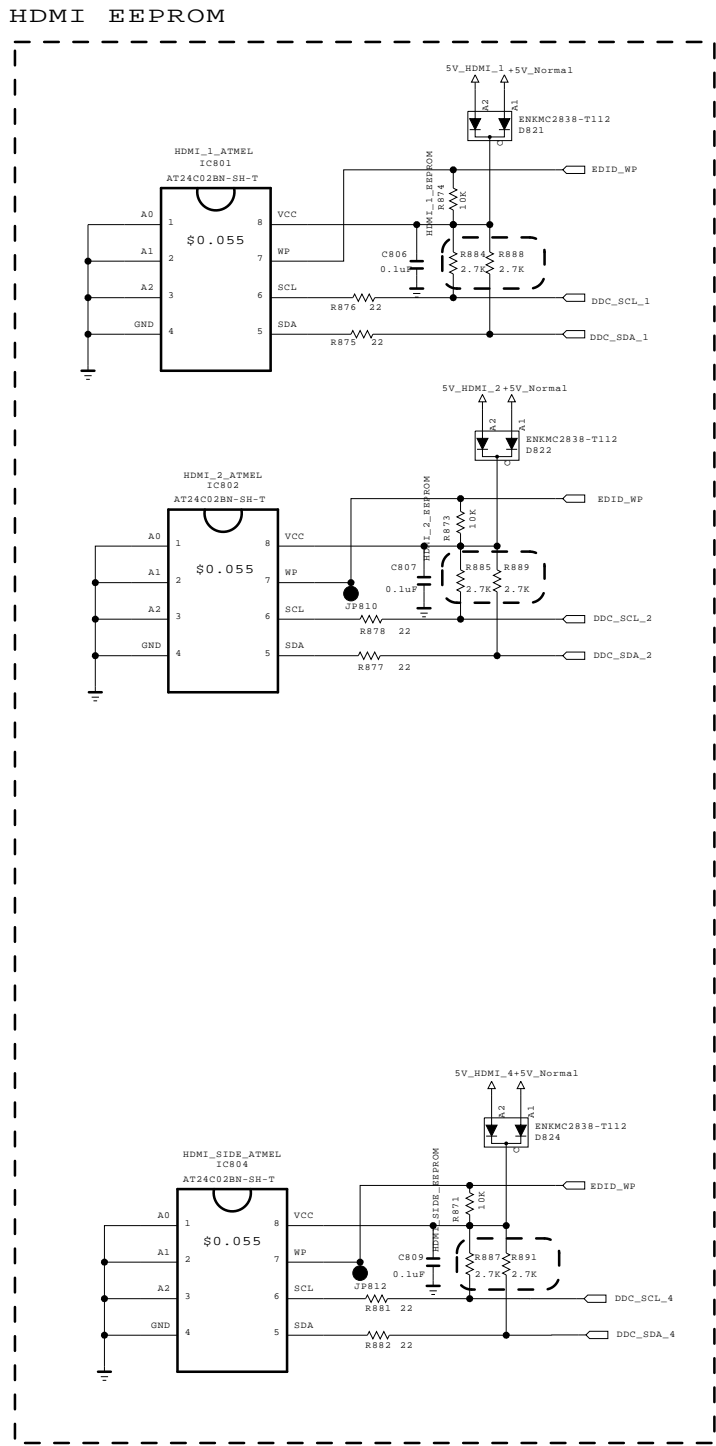
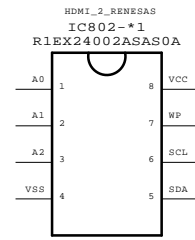
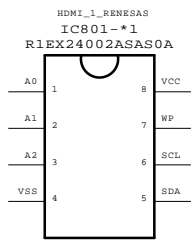
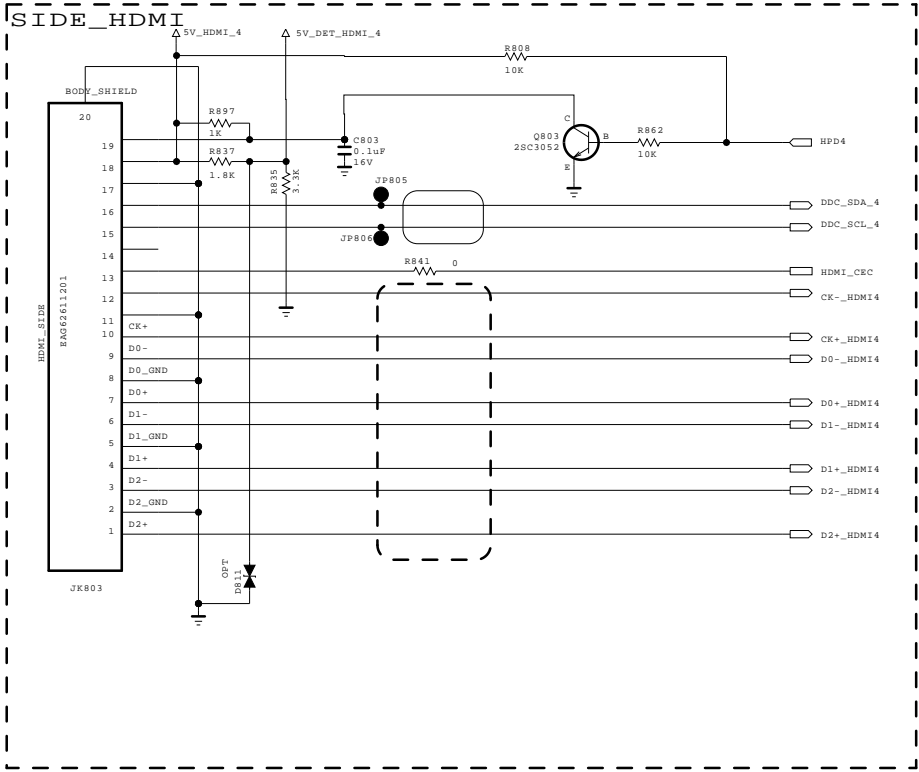
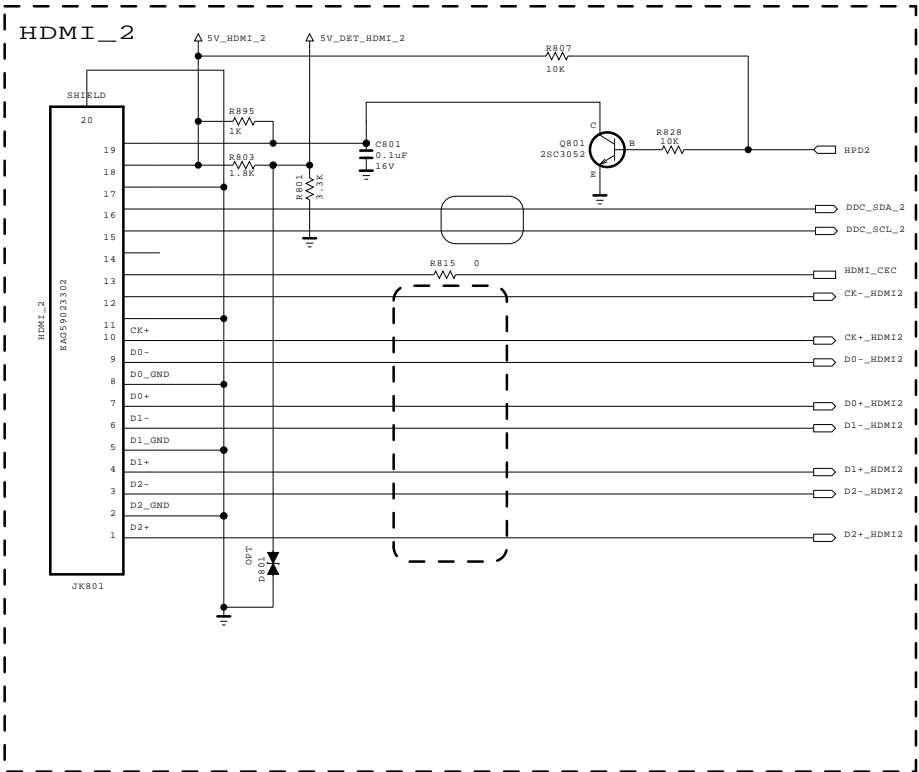
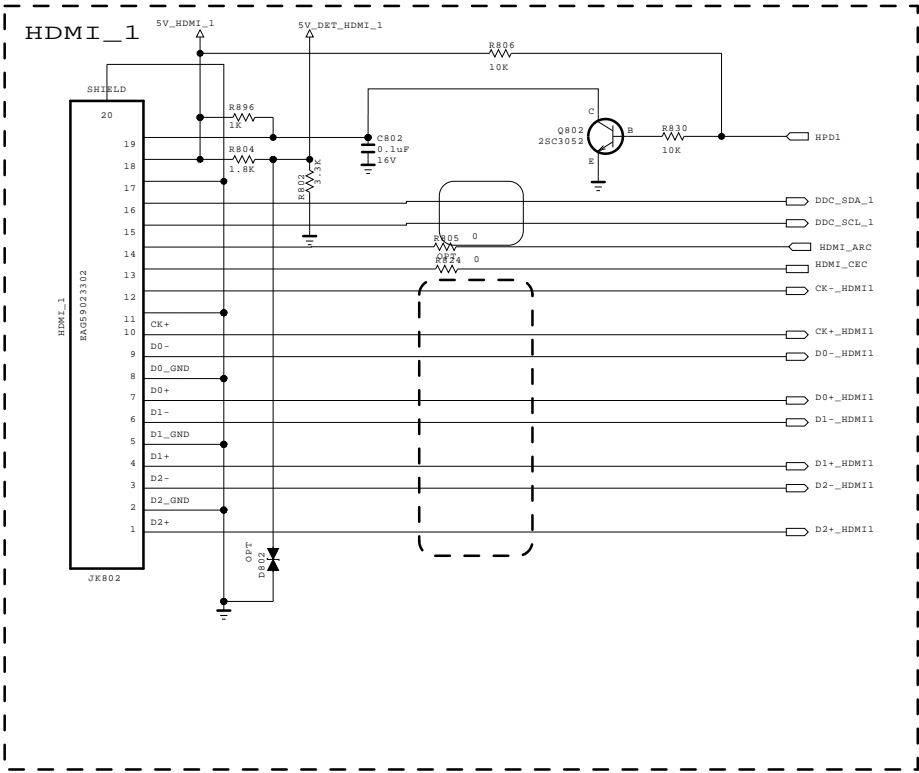


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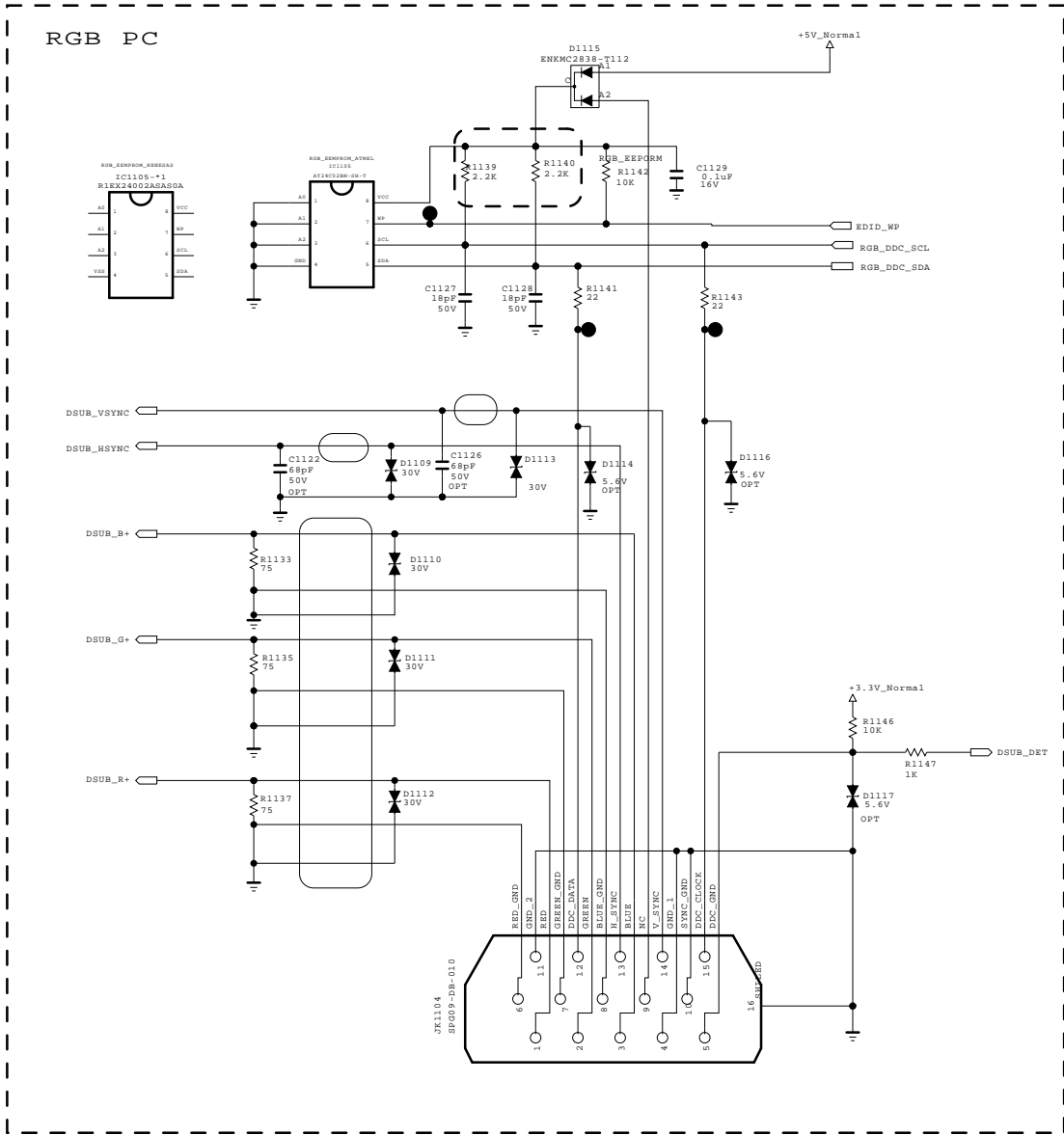
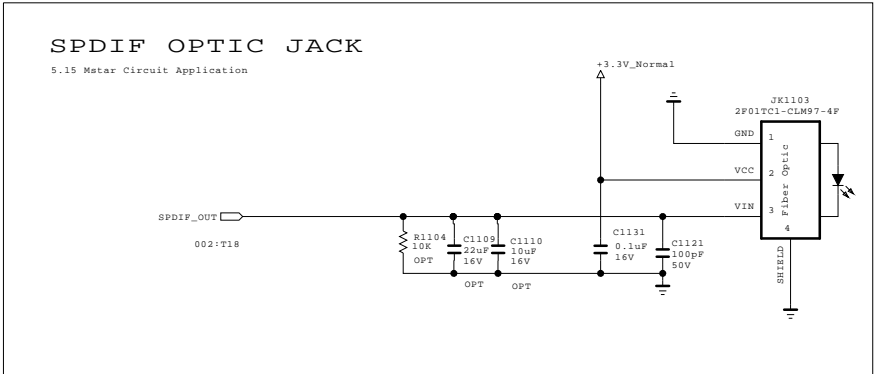
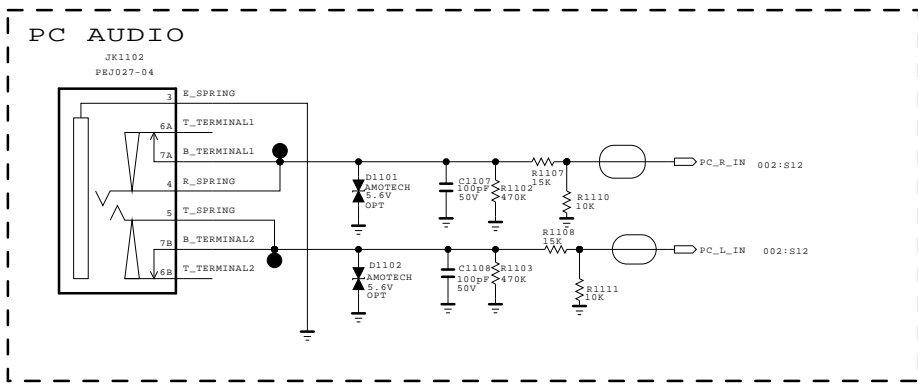
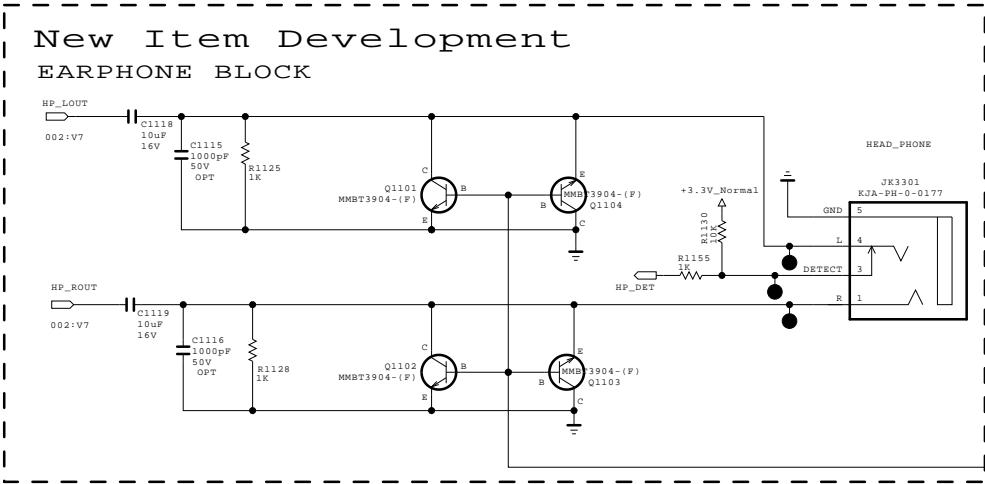
SECRET
LGElectronics





MODEL	GP3_S7LR	DATE	20110324
BLOCK	IR/CONTROL-L	SHEET	6 /



RGB / SPDIF / PC / HP

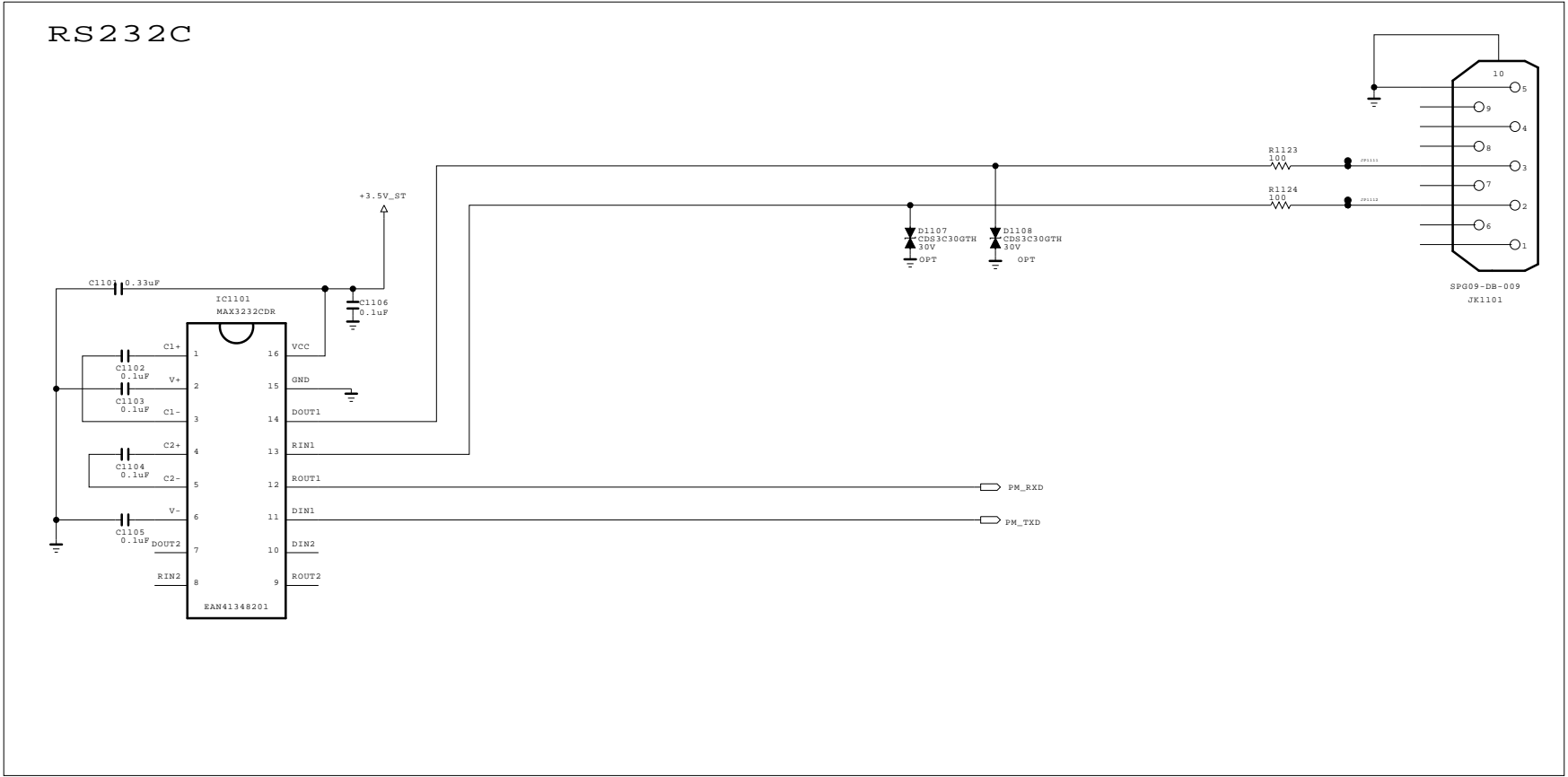




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MODEL	GP3_S7LR	DATE	20110324
BLOCK	RGB / SPDIF / HP	SHEET	9 /



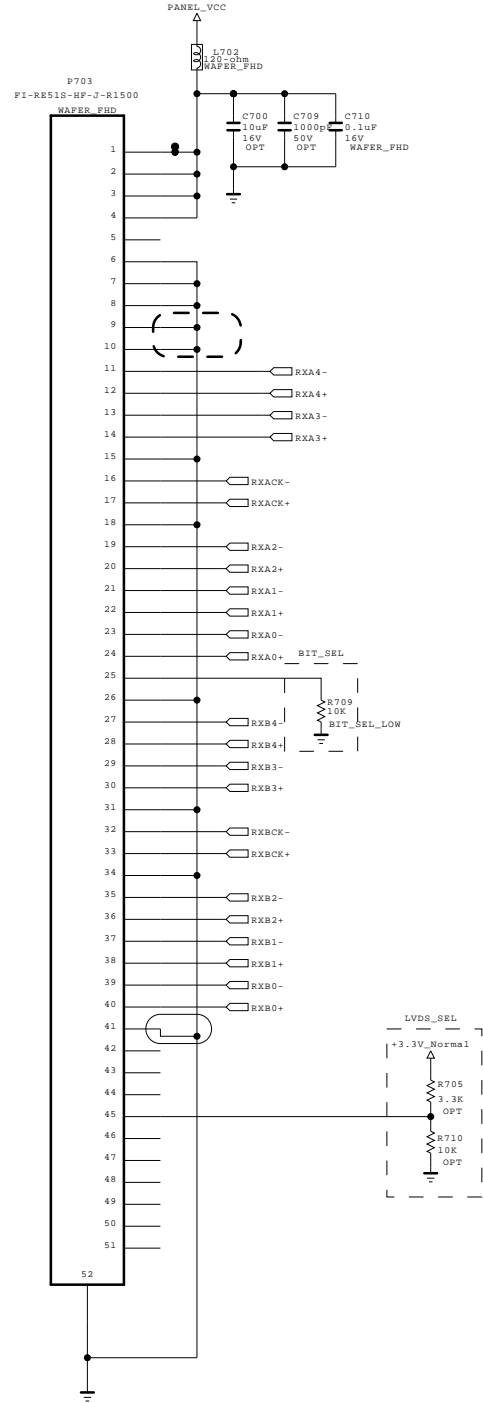
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SECRET
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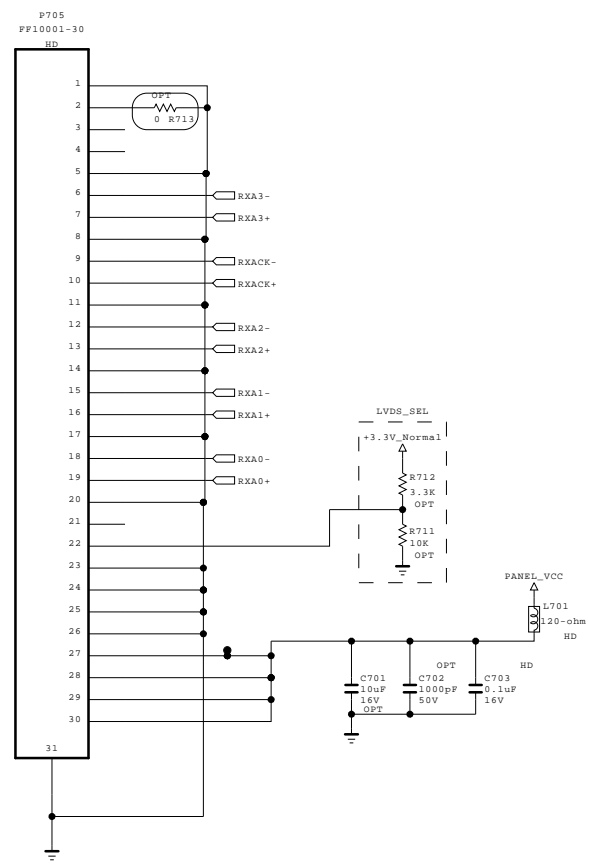




MODEL	GP3_S7LR	DATE	20110324
BLOCK	RS232C_9PIN	SHEET	10 /

[51Pin LVDS Connector]
(For FHD 60/120Hz)



[30Pin LVDS Connector]
(For HD 60Hz_Normal)

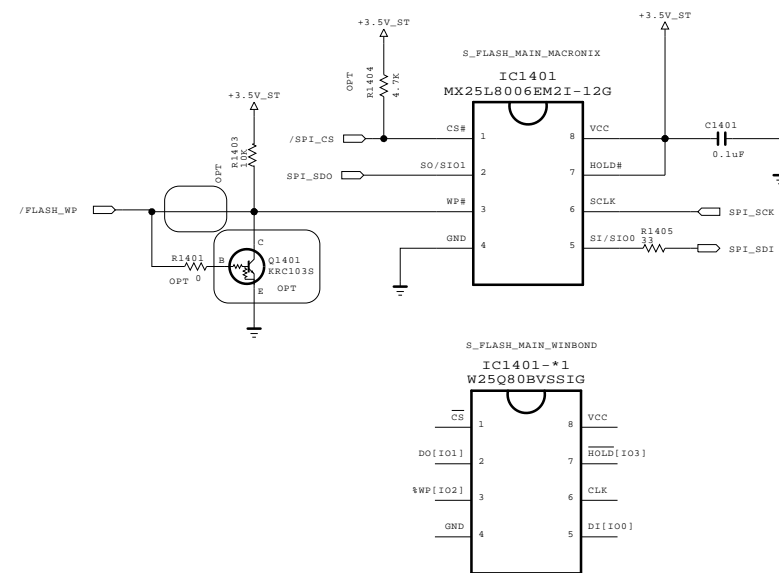




THE  SYMBOL MARK OF THIS SCHEMATIC DIAGRAM INCORPORATES SPECIAL FEATURES IMPORTANT FOR PROTECTION FROM X-RADIATION. FILRE AND ELECTRICAL SHOCK HAZARDS, WHEN SERVICING IF IS ESSENTIAL THAT ONLY MANUFACTURES SPECIFIED PARTS BE USED FOR THE CRITICAL COMPONENTS IN THE  SYMBOL MARK OF THE SCHEMATIC.

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MODEL	GP3_S7LR	DATE	20110324
BLOCK	LVDS_LARGE	SHEET	11 /



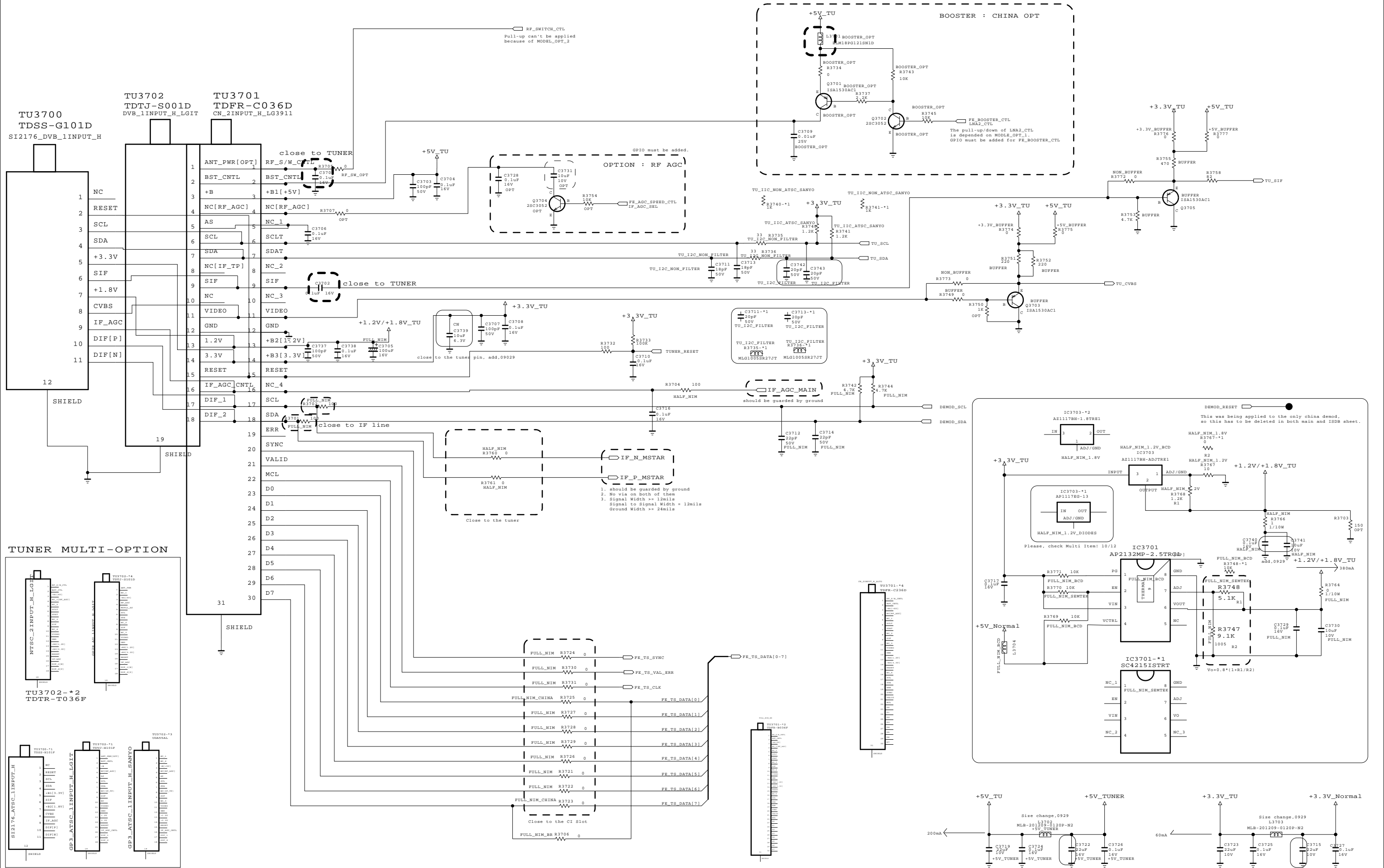
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

SECRET
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MODEL	GP3 S7LR	DATE	20110324
BLOCK	SFLASH	SHEET	13 /

GP4R_GLOBAL_TUNER_BLOCK

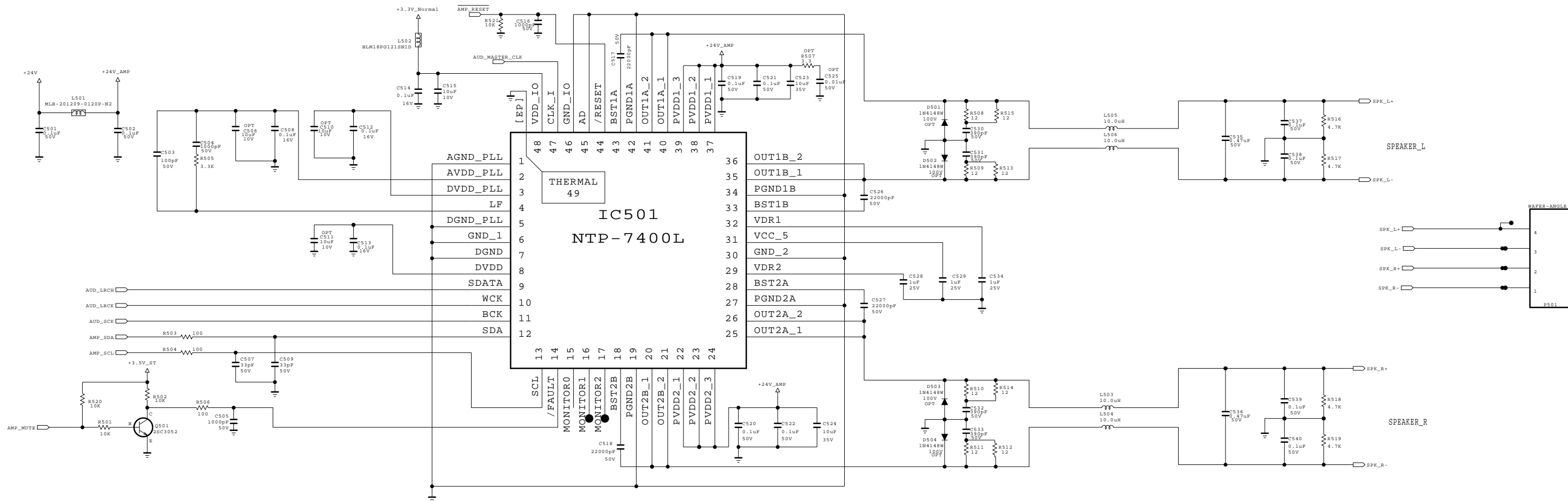




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MODEL	GP3_S7LR	DATE	20110511
BLOCK	TUNER_I	SHEET	14 /



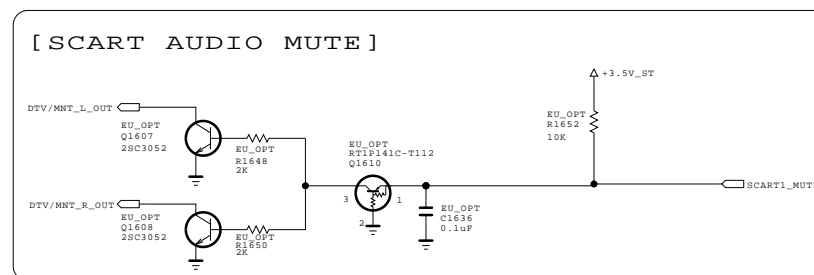
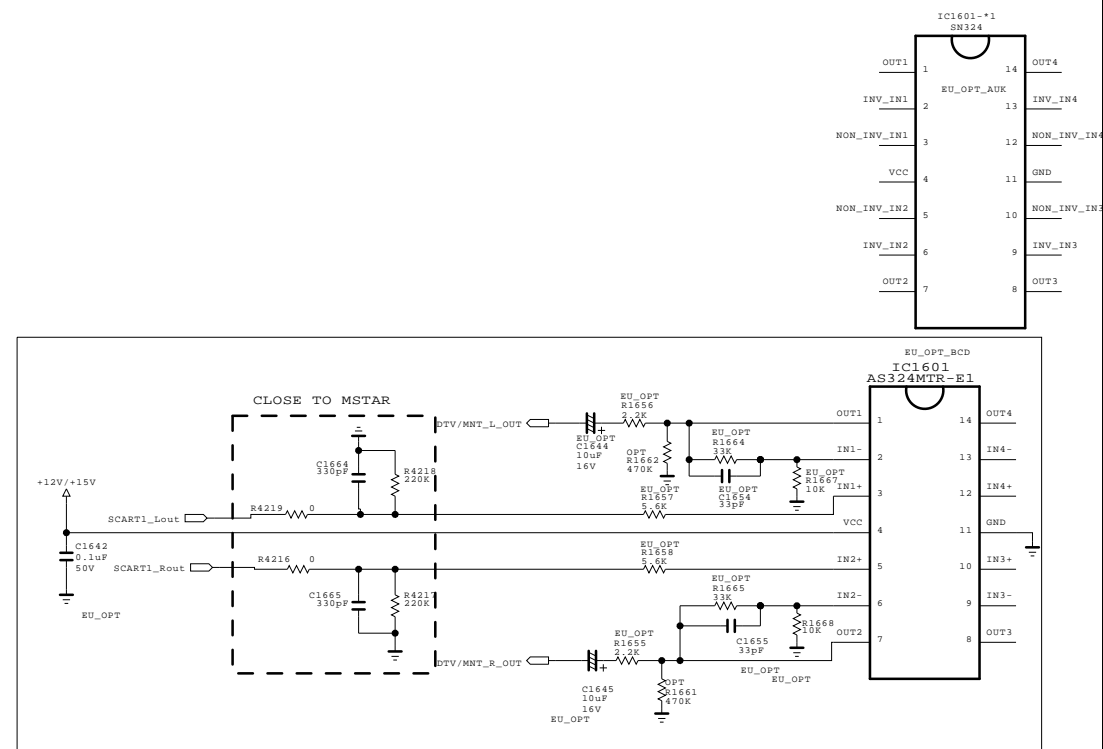
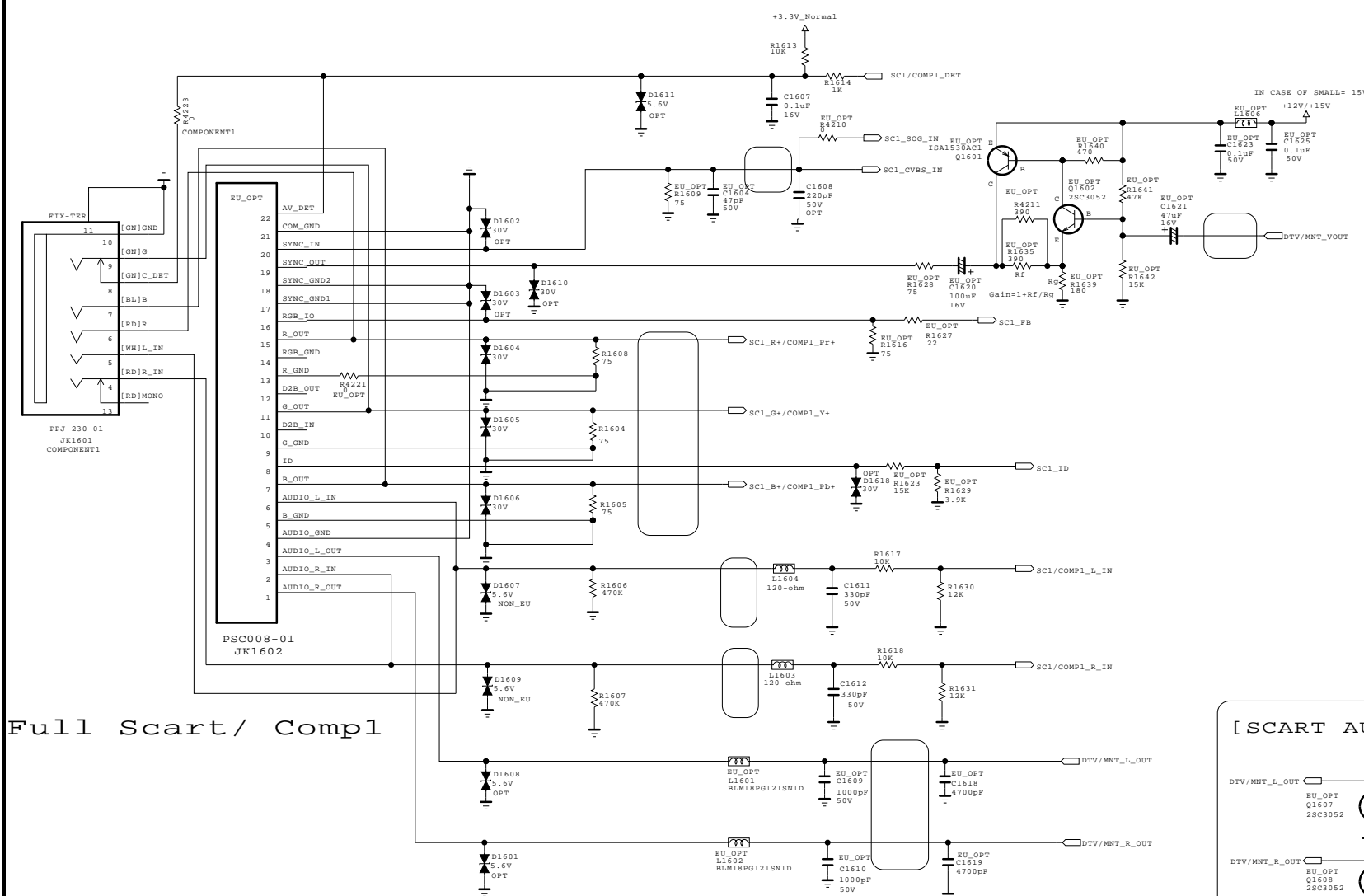
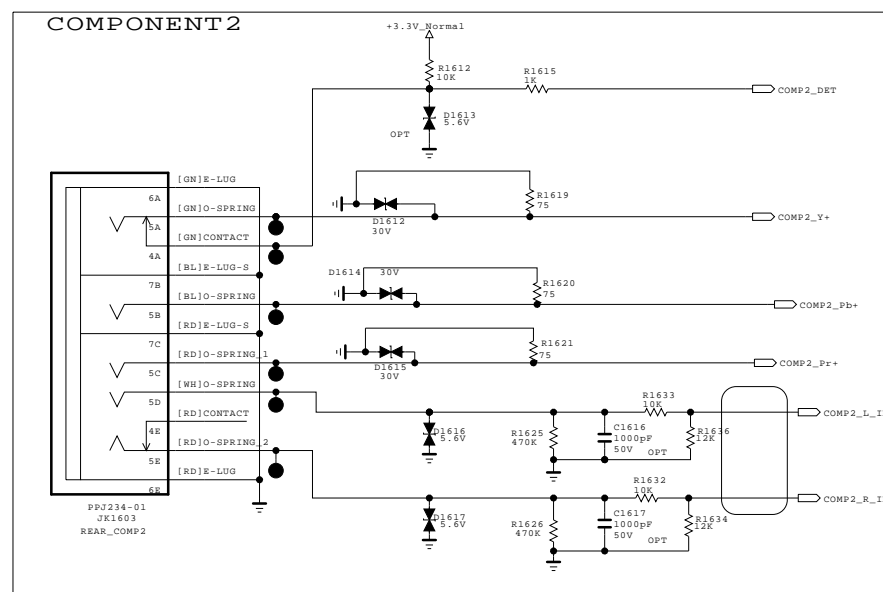
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MODEL	GP3 S7LR	DATE	20110324
BLOCK	NTP7400	SHEET	16 /

The schematic diagram illustrates the rear audio amplifier section. It begins with a JFET pre-amplifier stage (JF1604 PPT223-01) with pins 5C, 4C, 3C, 4B, 3A, 4A, and 5A. The circuit is powered by a 3.3V regulator (R1654, C1648, C1649) and a 5.6V regulator (R1672, R1673, C1662). The output stage uses a MOSFET (D1625) driven by a 470K resistor (R1672) and a 10K resistor (R1673). The output is connected to the rear speakers (REAR_AV) and the subwoofer (L_MONO). The circuit also includes a 3.3V regulator (R1654, C1648, C1649) and a 5.6V regulator (R1672, R1673, C1662).



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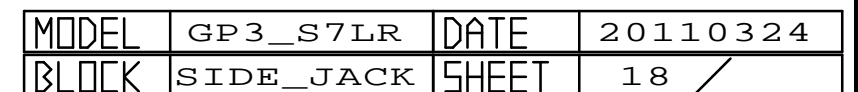


MODEL	GP3 S7LR	DATE	20110324
BLOCK	REAR JACK	SHEET	17 /

[illegible]

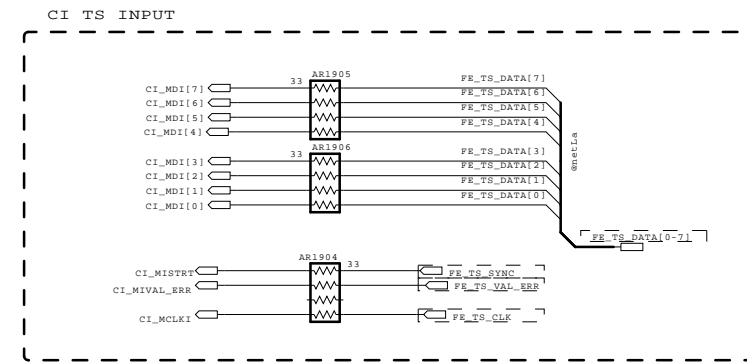
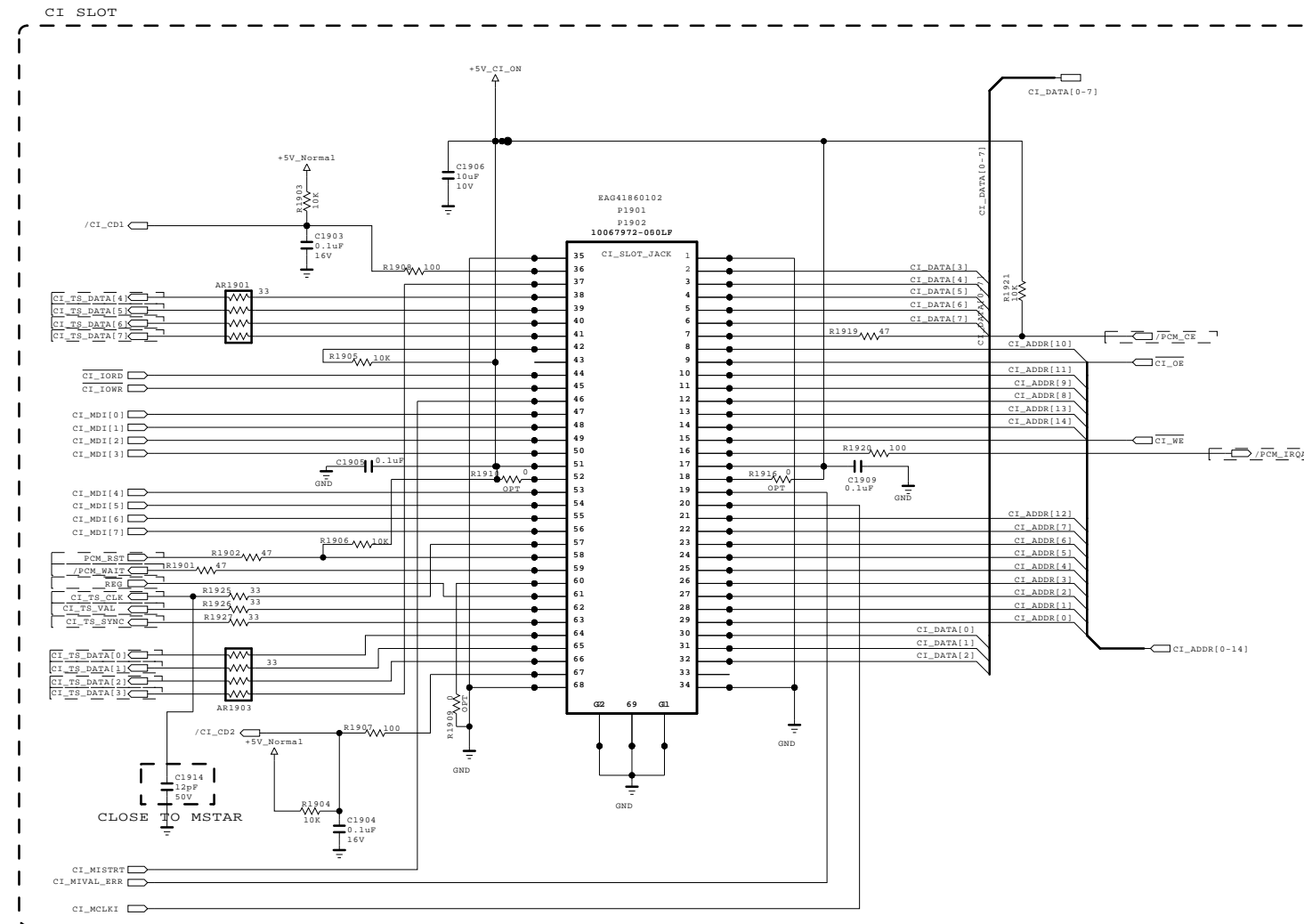
The schematic diagram illustrates the detection circuit for the JKE902 module. The module's pins are connected as follows: Pin 1 (M1) to the input of the first diode (D8907), Pin 2 (M3_DETECT) to the input of the second diode (D8905), Pin 3 (M4) to the input of the third diode (D8906), Pin 4 (M5_GND) to ground, and Pin 5 (M6) to the input of the fourth diode (D8908). The circuit is powered by a +3.3V_Nom1 supply. The output signals are COMP2_DET, COMP2_Y+, COMP2_Pb+, and COMP2_Pr+.

SECRET
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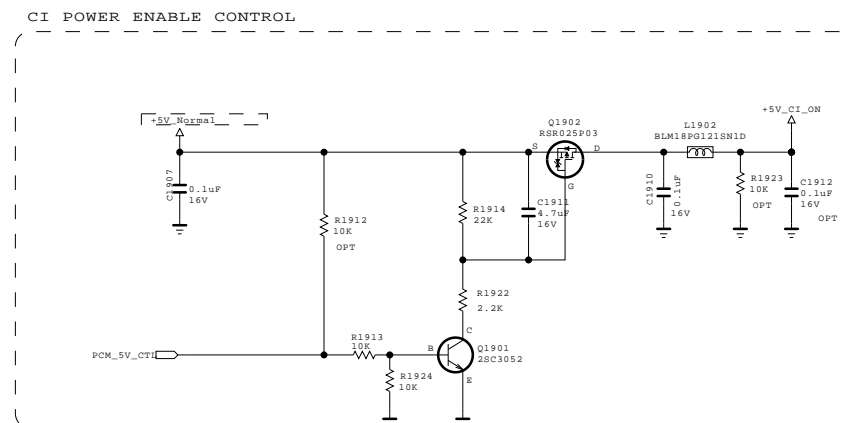
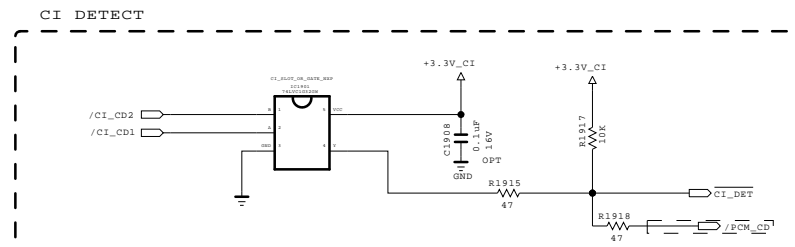
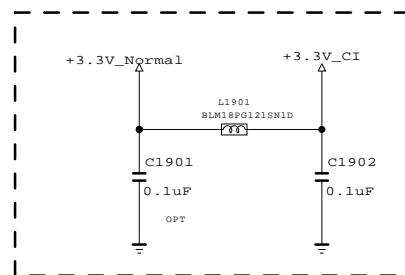
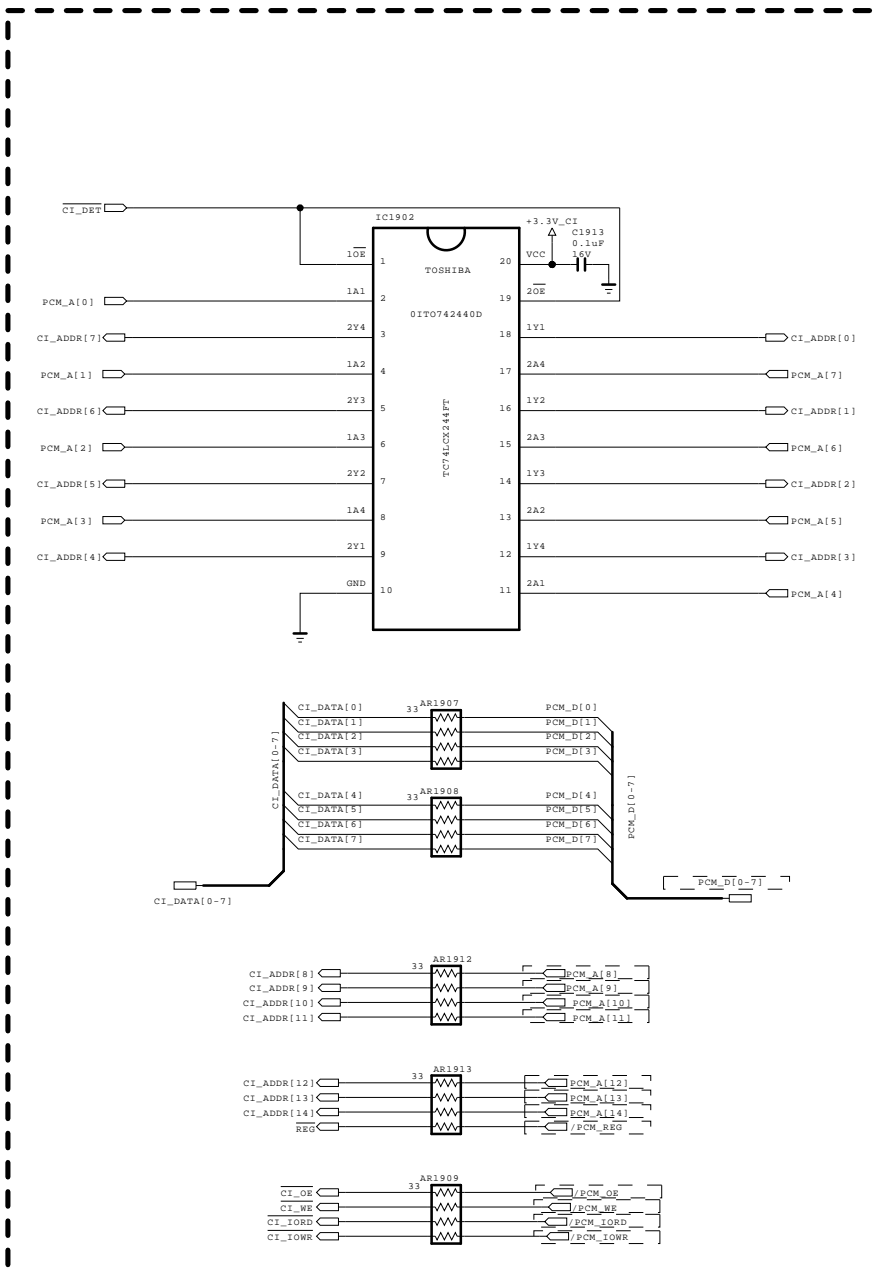


CI Region

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* Option name of this page : CI_SLOT
(because of Hong Kong)
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CI HOST I/F



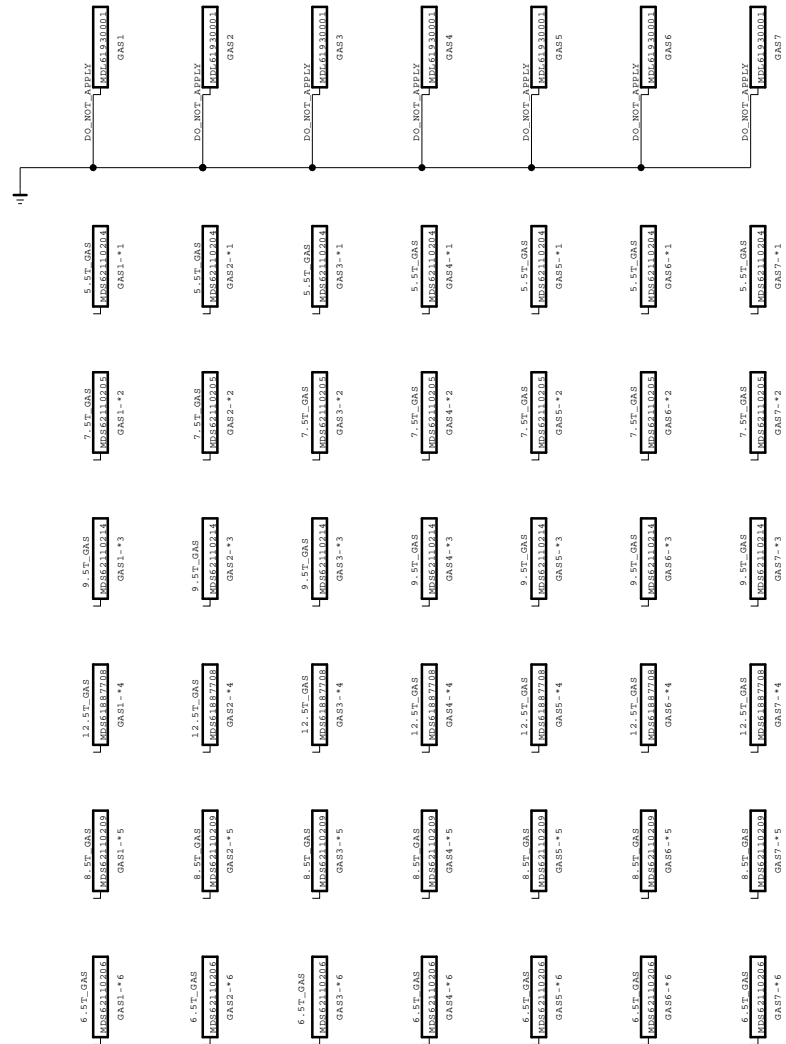
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MODEL	GP3_S7LR	DATE	20110324
FIG. NO.	PCMCI	SHEET	20 /

SMD GASKET



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SECRET
LGElectronics



MODEL	GP3_S7LR	DATE	20110324
BLOCK	SMD_GAS	SHEET	20 /

